

# TPS65251-x 4.5V~18V 入力、大電流、FET 内蔵、同期整流降圧 3 バック・スイッチャ

## 1 特長

- 広い入力電源電圧範囲 (4.5V~18V)
- 出力電圧範囲: 0.8V~ $V_{IN}-1V$
- 連続負荷: 3A (降圧 1)、2A (降圧 2 および 3)
- 最大電流: 3.5A (降圧 1)、2.5A (降圧 2 および 3)
- 可変スイッチング周波数  
外付け抵抗により 300kHz~2.2MHz に設定
- 降圧回路ごとの専用イネーブル
- 発振器用の外部同期ピン
- 外付け抵抗で電流制限を変更可能
- ソフトスタート・ピン
- シンプルな補償回路を使用する電流モード制御機能
- パワー・グッド
- PFM/PWM の自動切り替え動作
- VQFN パッケージ、40 ピン、6mm × 6mm、RHA (放射線耐性保証)

## 2 アプリケーション

- セット・トップ・ボックス
- Blu-ray™ DVD
- DVR
- DTV
- 車内用オーディオおよびビデオ
- セキュリティ・カメラ

## 3 概要

TPS65251-x には、入力電圧範囲が広く高効率の同期整流降圧コンバータが 3 個搭載されています。これらのコンバータは、アプリケーションを簡素化するとともに、対象アプリケーションに応じて使用方法を最適化できるように設計されています。

コンバータは、5、9、12、15V のシステムで動作し、パワー・トランジスタが内蔵されています。出力電圧は外付け

の分圧抵抗を使用して、0.8V から入力電源電圧近くまでの任意の値に設定できます。各コンバータにはイネーブル・ピンがあり、シーケンシングの目的で遅延スタートアップが可能です。ソフトスタート・ピンでソフトスタート・コンデンサを選択することによりソフトスタート時間を変更でき、電流制限 (RLIMx) ピンで外付け抵抗を選択するとともに最適なインダクタを選択して、電流制限を設定できます。電流モード制御によって、RC 補償が簡単になります。

コンバータのスイッチング周波数は、ROSC ピンに接続される外付け抵抗で設定するか、または必要に応じて SYNC ピンに接続される外部クロックに同期させることもできます。スイッチング・レギュレータは、300kHz~2.2MHz で動作するように設計されています。降圧 1 と降圧 2、3 は 180° の位相差で動作するため (降圧 2 と降圧 3 は同相動作)、入力フィルタの要件が最小限になります。

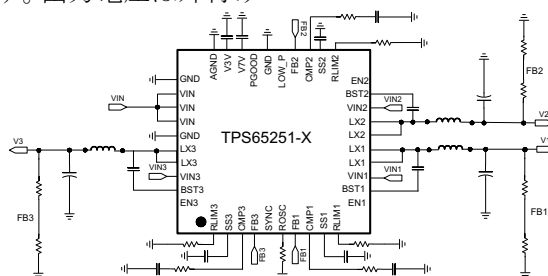
TPS65251-x にはスーパバイザ回路があり、各コンバータの出力を監視します。シーケンシングが完了し、すべての PG 信号が通知され、選択可能リセット終了時間が経過すると、PGOOD ピンがアサートされます。PGOOD 信号の極性は、アクティブ HIGH です。

すべてのコンバータには自動の低消費電力パルス PFM スキップ・モードが搭載されているため、軽負荷やスタンバイ動作時の効率が向上し、同時に非常に小さな出力リップルが保証され、低い出力電圧で 2% 未満という値を実現できます。

### 製品情報

| 部品番号       | パッケージ <sup>(1)</sup> | 本体サイズ (公称)      |
|------------|----------------------|-----------------|
| TPS65251-1 | VQFN (40)            | 6.00mm × 6.00mm |
| TPS65251-2 |                      |                 |
| TPS65251-3 |                      |                 |

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



## Table of Contents

|  |    |  |    |
|--|----|--|----|
| <b>1 特長</b> .....                              | 1  | 7.3 Feature Description.....                                     | 12 |
| <b>2 アプリケーション</b> .....                        | 1  | 7.4 Device Functional Modes.....                                 | 15 |
| <b>3 概要</b> .....                              | 1  | <b>8 Application and Implementation</b> .....                    | 16 |
| <b>4 Revision History</b> .....                | 2  | 8.1 Application Information.....                                 | 16 |
| <b>5 Pin Configuration and Functions</b> ..... | 3  | 8.2 Typical Application.....                                     | 16 |
| <b>6 Specifications</b> .....                  | 5  | <b>9 Power Supply Recommendations</b> .....                      | 29 |
| 6.1 Absolute Maximum Ratings.....              | 5  | <b>10 Layout</b> .....   | 30 |
| 6.2 ESD Ratings.....                           | 5  | 10.1 Layout Guidelines.....                                      | 30 |
| 6.3 Recommended Operating Conditions.....      | 5  | 10.2 Layout Example.....   | 31 |
| 6.4 Thermal Information.....                   | 5  | <b>11 Device and Documentation Support</b> .....                 | 32 |
| 6.5 Electrical Characteristics.....            | 6  | 11.1 Receiving Notification of Documentation Updates..           | 32 |
| 6.6 Typical Characteristics for Buck 1.....    | 8  | 11.2 サポート・リソース.....  | 32 |
| 6.7 Typical Characteristics for Buck 2.....    | 9  | 11.3 Trademarks.....   | 32 |
| 6.8 Typical Characteristics for Buck 3.....    | 10 | 11.4 Electrostatic Discharge Caution.....                        | 32 |
| <b>7 Detailed Description</b> .....            | 11 | 11.5 Glossary.....   | 32 |
| 7.1 Overview.....                              | 11 | <b>12 Mechanical, Packaging, and Orderable Information</b> ..... | 32 |
| 7.2 Functional Block Diagram.....              | 11 |  |    |

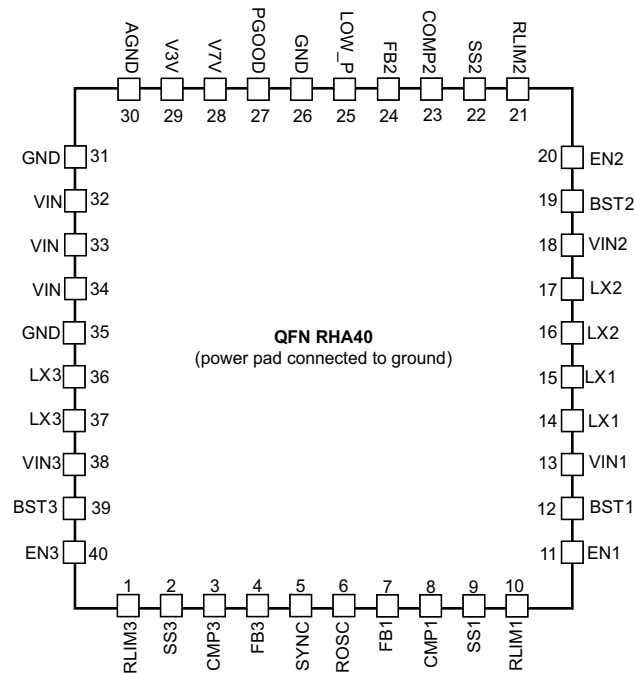
## 4 Revision History

| <b>Changes from Revision A (January 2015) to Revision B (January 2022)</b>                 | <b>Page</b> |
|--|-------------|
| • 文書全体にわたって表、図、相互参照の採番方法を更新.....   | 1           |
| • Change VIN1, VIN2, VIN3, LX1, LX2, and LX3 maximum rating voltage from 18 V to 20 V..... | 5           |
| • Change LX1, LX2, and LX3 minimum rating voltage from –1 V to –3 V.....                   | 5           |

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| <b>Changes from Revision * (January 2015) to Revision A (January 2015)</b> | <b>Page</b> |
|--|-------------|
| • デバイスのステータスを「量産データ」に更新.....   | 1           |

## 5 Pin Configuration and Functions



**表 5-1. Pin Functions**

| PIN   |     | I/O | DESCRIPTION  |
|-------|-----|-----|--|
| NAME  | NO. |     |  |
| RLIM3 | 1   | I   | Current limit setting for Buck 3. Fit a resistor from this pin to ground to set the peak current limit on the output inductor.   |
| SS3   | 2   | I   | Soft-start pin for Buck 3. Fit a small ceramic capacitor to this pin to set the converter soft-start time.   |
| COMP3 | 3   | O   | Compensation for Buck 3. Fit a series RC circuit to this pin to complete the compensation circuit of this converter.   |
| FB3   | 4   | I   | Feedback input for Buck 3. Connect a divider set to 0.8 V from the output of the converter to ground.  |
| SYNC  | 5   | I   | Synchronous clock input. If there is a sync clock in the system, connect to the pin. When not used, connect to GND.  |
| ROSC  | 6   | I   | Oscillator set. This resistor sets the frequency of the internal autonomous clock. If external synchronization is used, the resistor should be fitted and set to about 70% of external clock frequency.                            |
| FB1   | 7   | I   | Feedback pin for Buck 1. Connect a divider set to 0.8 V from the output of the converter to ground.  |
| COMP1 | 8   | O   | Compensation pin for Buck 1. Fit a series RC circuit to this pin to complete the compensation circuit of this converter.   |
| SS1   | 9   | I   | Soft-start pin for Buck 1. Fit a small ceramic capacitor to this pin to set the converter soft-start time.   |
| RLIM1 | 10  | I   | Current limit setting pin for Buck 1. Fit a resistor from this pin to ground to set the peak current limit on the output inductor.   |
| EN1   | 11  | I   | Enable pin for Buck 1. A low-level signal on this pin disables it. If pin is left open, a weak internal pull-up to V3V allows for automatic enable. For a delayed start-up, add a small ceramic capacitor from this pin to ground. |
| BST1  | 12  | I   | Bootstrap capacitor for Buck 1. Fit a 47-nF ceramic capacitor from this pin to the switching node.   |
| VIN1  | 13  | I   | Input supply for Buck 1. Fit a 10- $\mu$ F ceramic capacitor close to this pin.  |
| LX1   | 14  | O   | Switching node for Buck 1  |
|       | 15  |     |  |
| LX2   | 16  | O   | Switching node for Buck 2  |
|       | 17  |     |  |
| VIN2  | 18  | I   | Input supply for Buck 2. Fit a 10- $\mu$ F ceramic capacitor close to this pin.  |
| BST2  | 19  | I   | Bootstrap capacitor for Buck 2. Fit a 47-nF ceramic capacitor from this pin to the switching node.   |

表 5-1. Pin Functions (continued)

| PIN   |     | I/O | DESCRIPTION  |
|-------|-----|-----|--|
| NAME  | NO. |     |  |
| EN2   | 20  | I   | Enable pin for Buck 2. A low-level signal on this pin disables it. If pin is left open, a weak internal pull-up to V3V allows for automatic enable. For a delayed start-up, add a small ceramic capacitor from this pin to ground. |
| RLIM2 | 21  | I   | Current limit setting for Buck 2. Fit a resistor from this pin to ground to set the peak current limit on the output inductor.   |
| SS2   | 22  | I   | Soft-start pin for Buck 2. Fit a small ceramic capacitor to this pin to set the converter soft-start time.   |
| COMP2 | 23  | O   | Compensation pin for Buck 2. Fit a series RC circuit to this pin to complete the compensation circuit of this converter  |
| FB2   | 24  | I   | Feedback input for Buck 2. Connect a divider set to 0.8 V from the output of the converter to ground.  |
| LOW_P | 25  | I   | Low-power operation mode (active-high) input for TPS65251  |
| GND   | 26  |     | Ground pin   |
| PGOOD | 27  | O   | Power good. Open-drain output asserted after all converters are sequenced and within regulation. Polarity is factory selectable (active-high default).   |
| V7V   | 28  | O   | Internal supply. Connect a 10- $\mu$ F ceramic capacitor from this pin to ground.  |
| V3V   | 29  | O   | Internal supply. Connect a 3.3- to 10- $\mu$ F ceramic capacitor from this pin to ground.  |
| AGND  | 30  |     | Analog ground. Connect all GND pins and the power pad together.  |
| GND   | 31  |     | Ground pin   |
| VIN   | 32  | I   | Input supply   |
|       | 33  |     |  |
|       | 34  |     |  |
| GND   | 35  |     | Ground pin   |
| LX3   | 36  | O   | Switching node for Buck 3  |
|       | 37  |     |  |
| VIN3  | 38  |     | Input supply for Buck 3. Fit a 10- $\mu$ F ceramic capacitor close to this pin.  |
| BST3  | 39  | I   | Bootstrap capacitor for Buck 3. Fit a 47-nF ceramic capacitor from this pin to the switching node.   |
| EN3   | 40  | I   | Enable pin for Buck 3. A low-level signal on this pin disables it. If pin is left open, a weak internal pull-up to V3V allows for automatic enable. For a delayed start-up, add a small ceramic capacitor from this pin to ground. |
| PAD   | —   | —   | Power pad. Connect to ground.  |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|                  |  | MIN  | MAX | UNIT |
|------------------|--|------|-----|------|
| Voltage          | VIN1, VIN2, VIN3, LX1, LX2, LX3  | -0.3 | 20  | V    |
|                  | LX1, LX2, LX3 (maximum withstand voltage transient <10 ns)   | -3   | 23  | V    |
|                  | BST1, BST2, BST3, referenced to Lx pin   | -0.3 | 7   | V    |
|                  | V7V  | -0.3 | 7   | V    |
|                  | V3V, RLIM1, RLIM2, RLIM3, EN1, EN2, EN3, SS1, SS2, SS3, FB1, FB2, FB3, PGOOD, SYNC, ROSC, RST_IN, LOW_P, COMP1, COMP2, COMP3 | -0.3 | 3.6 | V    |
|                  | AGND, GND  | -0.3 | 0.3 | V    |
| T <sub>J</sub>   | Operating virtual junction temperature   | -40  | 125 | °C   |
| T <sub>stg</sub> | Storage temperature  | -55  | 150 | °C   |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

|                    |                         |  | VALUE | UNIT |
|--------------------|-------------------------|--|-------|------|
| V <sub>(ESD)</sub> | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>              | ±2000 | V    |
|                    |                         | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup> | ±500  |      |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

|                 |                         | MIN | NOM | MAX | UNIT |
|-----------------|-------------------------|-----|-----|-----|------|
| V <sub>IN</sub> | Input operating voltage | 4.5 |     | 18  | V    |
| T <sub>J</sub>  | Junction temperature    | -40 |     | 125 | °C   |

### 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |  | TPS65251-x | UNIT |
|-------------------------------|--|------------|------|
|                               |  | RHA        |      |
|                               |  | 40 PINS    |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 32.7       | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 21.4       |      |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 8.3        |      |
| ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 0.2        |      |
| ψ <sub>JB</sub>               | Junction-to-board characterization parameter | N/A        |      |
| R <sub>θJC(bot)</sub>         | Junction-to-case (bottom) thermal resistance | 2          |      |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

 $T_J = -40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ ,  $V_{IN} = 12\text{ V}$ ,  $f_{SW} = 500\text{ Hz}$  (unless otherwise noted)

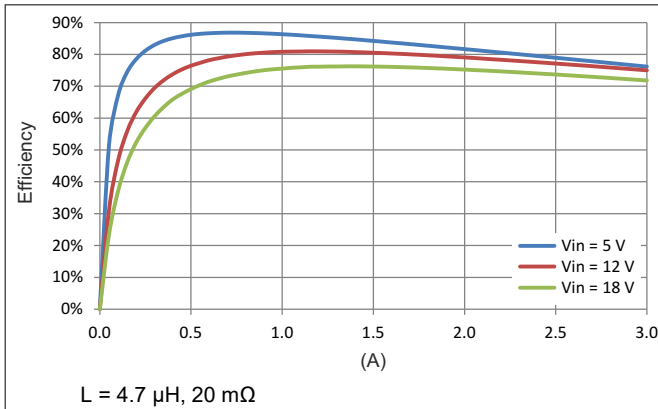
| PARAMETER  |                                     | TEST CONDITIONS   | MIN                   | TYP  | MAX  | UNIT          |
|--|-------------------------------------|---|-----------------------|------|------|---------------|
| <b>INPUT SUPPLY UVLO AND INTERNAL SUPPLY VOLTAGE</b>   |                                     |   |                       |      |      |               |
| $V_{IN}$   | Input voltage range                 |   | 4.5                   |      | 18   | V             |
| $I_{DDSDN}$  | Shutdown                            | EN pin = Low for all converters   |                       | 175  |      | $\mu\text{A}$ |
| $I_{DDQ}$  | Quiescent, low power disabled (Lo)  | Converters enabled, no load<br>Buck 1 = 3.3 V, Buck 2 = 2.5 V, Buck 3 = 7.5 V,<br>L = 4.7 $\mu\text{H}$ , $f_{SW} = 800\text{ kHz}$ |                       | 20   |      | mA            |
| $I_{DDQ\_LOW\_P}$  | Quiescent, low power enabled (Hi)   | Converters enabled, no load<br>Buck 1 = 3.3 V, Buck 2 = 2.5 V, Buck 3 = 7.5 V,<br>L = 4.7 $\mu\text{H}$ , $f_{SW} = 800\text{ kHz}$ |                       | 1    |      | mA            |
| $UVLO_{VIN}$   | $V_{IN}$ undervoltage lockout       | Rising $V_{IN}$   |                       | 4.22 |      | V             |
|  |                                     | Falling $V_{IN}$  |                       | 4.1  |      | V             |
| $UVLO_{DEGLITCH}$  |                                     | Both edges  |                       | 110  |      | $\mu\text{s}$ |
| $V_{3p3}$  | Internal biasing supply             |   |                       | 3.3  |      | V             |
| $V_{7V}$   | Internal biasing supply             |   |                       | 6.25 |      | V             |
| $V_{7VUVLO}$   | UVLO for internal V7V rail          | Rising V7V  |                       | 3.8  |      | V             |
|  |                                     | Falling V7V   |                       | 3.6  |      | V             |
| $V_{7VUVLO\_DEGLITCH}$   |                                     | Falling edge  |                       | 110  |      | $\mu\text{s}$ |
| <b>BUCK CONVERTERS (ENABLE CIRCUIT, CURRENT LIMIT, SOFT START, SWITCHING FREQUENCY AND SYNC CIRCUIT, LOW POWER MODE)</b> |                                     |   |                       |      |      |               |
| $V_{IH}$   | Enable threshold high               | External GPIO mode, $V_{3p3} = 3.2$ to $3.4\text{ V}$   | $0.66 \times V_{3p3}$ |      |      | V             |
|  | Enable high level                   | $V_{3p3} = 3.2$ to $3.4\text{ V}$ , $V_{ENX}$ rising  | 1.55                  | 1.67 | 1.82 |               |
| $V_{IL}$   | Enable threshold low                | External GPIO mode, $V_{3p3} = 3.2$ to $3.4\text{ V}$   | $0.33 \times V_{3p3}$ |      |      | V             |
|  | Enable low level                    | $V_{3p3} = 3.2$ to $3.4\text{ V}$ , $V_{ENX}$ falling   | 0.98                  | 1.10 | 1.24 |               |
| $R_{EN\_DIS}$  | Enable discharge resistor           |   | -25%                  | 2.1  | 25%  | k $\Omega$    |
| $I_{CHEN}$   | Pullup current enable pin           |   |                       | 1.1  |      | $\mu\text{A}$ |
| $t_D$  | Discharge time enable pins          | Power-up  |                       | 10   |      | ms            |
| $I_{SS}$   | Soft-start pin current source       |   |                       | 5    |      | $\mu\text{A}$ |
| $F_{SW\_BK}$   | Converter switching frequency range | Set externally with resistor  | 0.3                   |      | 2.2  | MHz           |
| $R_{FSW}$  | Frequency setting resistor          | Depending on set frequency  | 50                    |      | 600  | k $\Omega$    |
| $f_{SW\_TOL}$  | Internal oscillator accuracy        | $f_{SW} = 800\text{ kHz}$   | -10%                  |      | 10%  |               |
| $V_{SYNCH}$  | External clock threshold high       | $V_{3p3} = 3.3\text{ V}$  |                       |      | 1.24 | V             |
| $V_{SYNCL}$  | External clock threshold low        | $V_{3p3} = 3.3\text{ V}$  | 1.55                  |      |      | V             |
| $SYNCRANGE$  | Synchronization range               |   | 0.2                   |      | 2.2  | MHz           |
| $SYNCLK\_MIN$  | Sync signal minimum duty cycle      |   | 40%                   |      |      |               |
| $SYNCLK\_MAX$  | Sync signal maximum duty cycle      |   |                       |      | 60%  |               |
| $V_{H\_LOW\_P}$  | Low power mode threshold high       | $V_{3p3} = 3.3\text{ V}$ , $V_{ENX}$ rising   | 1.55                  |      |      | V             |
| $V_{L\_LOW\_P}$  | Low power mode threshold Low        | $V_{3p3} = 3.3\text{ V}$ , $V_{ENX}$ falling  |                       |      | 1.24 | V             |

$T_J = -40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ ,  $V_{IN} = 12\text{ V}$ ,  $f_{SW} = 500\text{ Hz}$  (unless otherwise noted)

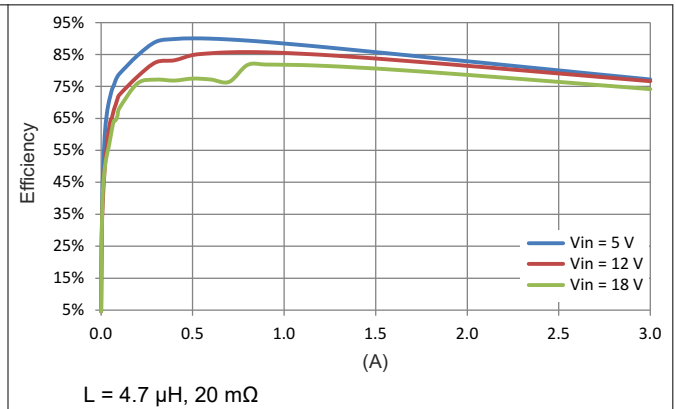
| PARAMETER                                 |   | TEST CONDITIONS   | MIN | TYP  | MAX | UNIT               |
|---|---|---|-----|------|-----|--------------------|
| <b>FEEDBACK, REGULATION, OUTPUT STAGE</b> |   |   |     |      |     |                    |
| $V_{FB}$                                  | Feedback voltage  | $V_{IN} = 12\text{ V}$ , $T_J = 25^{\circ}\text{C}$   | -1% | 0.8  | 1%  | V                  |
|   |   | $V_{IN} = 4.5$ to $18\text{ V}$   | -2% | 0.8  | 2%  |                    |
| $I_{FB}$                                  | Feedback leakage current  |   |     |      | 50  | nA                 |
| $t_{ON\_MIN}$                             | Minimum on-time (current sense blanking) to specify output regulation |   |     | 70   | 100 | ns                 |
| $RLIM_1$                                  | Limit resistance range  | $V_{IN} = 12\text{ V}$ , $f_{SW} = 500\text{ kHz}$  | 75  |      | 300 | k $\Omega$         |
| $RLIM_{2,3}$                              | Limit resistance range  | $V_{IN} = 12\text{ V}$ , $f_{SW} = 500\text{ kHz}$  | 1.1 |      | 5.1 | A                  |
| $ILIM_1$                                  | Buck1 current limit range   | $V_{IN} = 12\text{ V}$ , $f_{SW} = 500\text{ kHz}$  | 100 |      | 300 | k $\Omega$         |
| $ILIM_2$                                  | Buck2 current limit range   | $V_{IN} = 12\text{ V}$ , $f_{SW} = 500\text{ kHz}$  | 1.2 |      | 4.1 | A                  |
| $ILIM_3$                                  | Buck3 current limit range   | $V_{IN} = 12\text{ V}$ , $f_{SW} = 500\text{ kHz}$  | 1.2 |      | 4.1 | A                  |
| <b>MOSFET (BUCK 1)</b>                    |   |   |     |      |     |                    |
| H.S. Switch                               | Turn-on resistance high-side FET on CH1                               | BOOT = 6.5 V, $T_J = 25^{\circ}\text{C}$  |     | 95   |     | m $\Omega$         |
| L.S. Switch                               | Turn-on resistance low-side FET on CH1                                | $V_{IN} = 12\text{ V}$ , $T_J = 25^{\circ}\text{C}$   |     | 50   |     | m $\Omega$         |
| <b>MOSFET (BUCK 2)</b>                    |   |   |     |      |     |                    |
| H.S. Switch                               | Turn-on resistance high-side FET on CH2                               | BOOT = 6.5 V, $T_J = 25^{\circ}\text{C}$  |     | 120  |     | m $\Omega$         |
| L.S. Switch                               | Turn-on resistance low-side FET on CH2                                | $V_{IN} = 12\text{ V}$ , $T_J = 25^{\circ}\text{C}$   |     | 80   |     | m $\Omega$         |
| <b>MOSFET (BUCK 3)</b>                    |   |   |     |      |     |                    |
| H.S. Switch                               | Turn-on resistance high-side FET on CH3                               | BOOT = 6.5 V, $T_J = 25^{\circ}\text{C}$  |     | 120  |     | m $\Omega$         |
| L.S. Switch                               | Turn-on resistance low-side FET on CH3                                | $V_{IN} = 12\text{ V}$ , $T_J = 25^{\circ}\text{C}$   |     | 80   |     | m $\Omega$         |
| <b>ERROR AMPLIFIER</b>                    |   |   |     |      |     |                    |
| $g_M$                                     | Error amplifier transconductance                                      | $-2\text{ }\mu\text{A} < I_{COMP} < 2\text{ }\mu\text{A}$   |     | 130  |     | $\mu\text{mhos}$   |
| $g_{mPS}$                                 | COMP to ILX $g_M$   | ILX = 0.5 A   |     | 10   |     | A/V                |
| <b>POWER GOOD RESET GENERATOR</b>         |   |   |     |      |     |                    |
| $V_{UV\_BUCKX}$                           | Threshold voltage for buck under voltage                              | Output falling  |     | 85%  |     |                    |
|   |   | Output rising (PG is asserted)  |     | 90%  |     |                    |
| $t_{UV\_deglitch}$                        | Deglintch time (both edges)   | Each buck   |     | 11   |     | ms                 |
| $t_{ON\_HICCUP}$                          | Hiccup mode ON time   | $V_{UV\_BUCKX}$ asserted  |     | 13   |     | ms                 |
| $t_{OFF\_HICCUP}$                         | Hiccup mode OFF time  | All converters disabled. After $t_{OFF\_HICCUP}$ elapses, all converters go through sequencing again. |     | 11   |     | ms                 |
| $VOV\_BUCKX$                              | Threshold voltage for buck over voltage                               | Output rising (high-side FET is forced off)   |     | 106% |     |                    |
|   |   | Output falling (high-side FET is allowed to switch)   |     | 104% |     |                    |
| $t_{RP}$                                  | Minimum reset period  | TPS65251-1  |     | 1000 |     | ms                 |
|   |   | TPS65251-2  |     | 32   |     |                    |
|   |   | TPS65251-3  |     | 256  |     |                    |
| <b>THERMAL SHUTDOWN</b>                   |   |   |     |      |     |                    |
| $T_{TRIP}$                                | Thermal shutdown trip point   | Rising temperature  |     | 160  |     | $^{\circ}\text{C}$ |
| $T_{HYST}$                                | Thermal shutdown hysteresis   | Device restarts   |     | 20   |     | $^{\circ}\text{C}$ |
| $t_{TRIP\_DEGLITCH}$                      | Thermal shutdown deglitch   |   | 100 |      | 120 | $\mu\text{s}$      |

## 6.6 Typical Characteristics for Buck 1

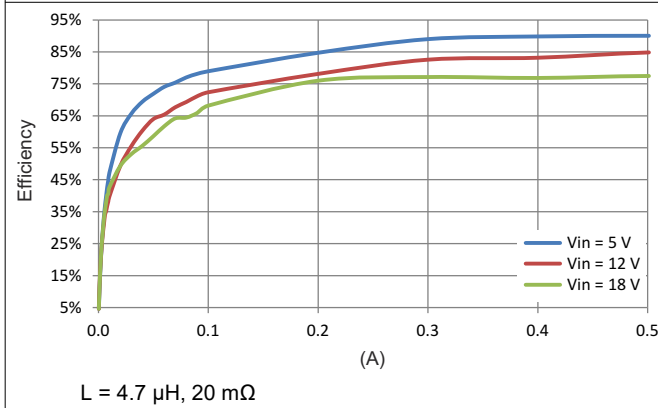
$T_A = 25^\circ\text{C}$ ,  $V_{IN} = 12\text{ V}$ ,  $V_O = 1.2\text{ V}$ ,  $L = 4.7\ \mu\text{H}$ ,  $C_O = 68\ \mu\text{F}$ ,  $f_{SW} = 500\text{ Hz}$  (unless otherwise noted)



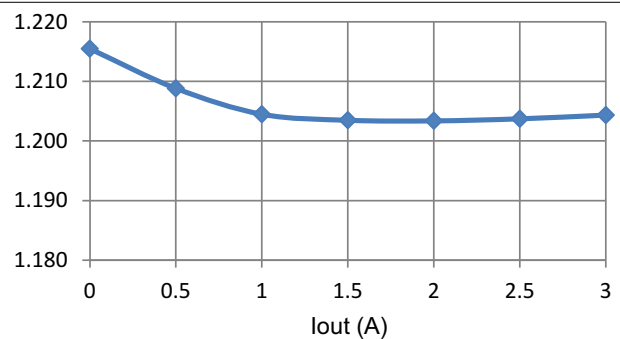
6-1. Efficiency, Forced PWM



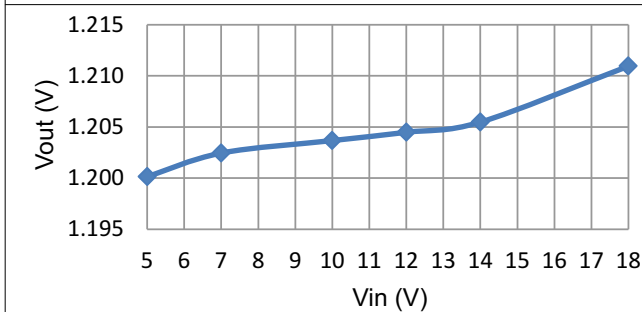
6-2. Efficiency, LOW\_P Mode



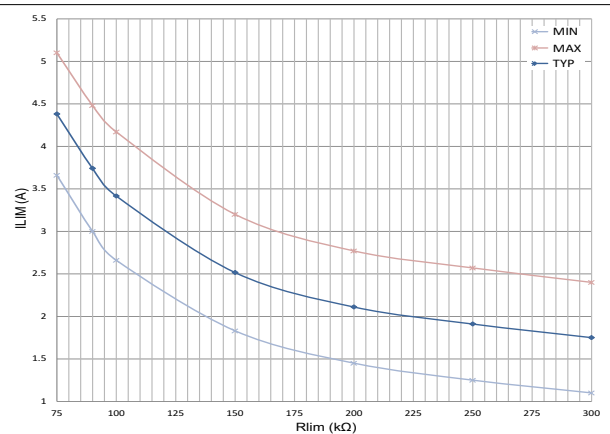
6-3. Efficiency, LOW\_P Mode, 0 to 500 mA



6-4. Load Regulation,  $25^\circ\text{C}$ , 1% 100-PPM Resistor



6-5. Line Regulation, Load = 1 A

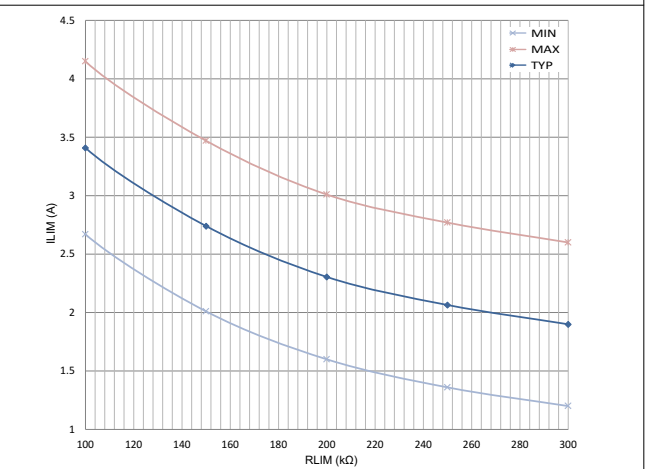
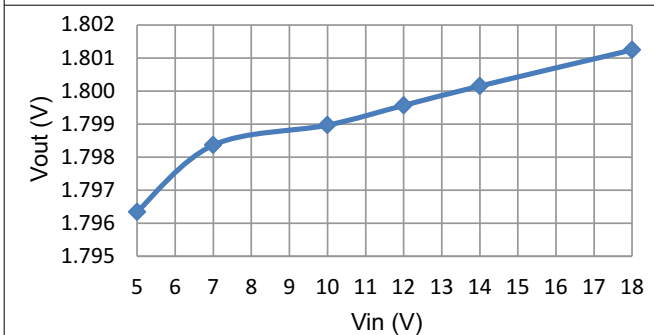
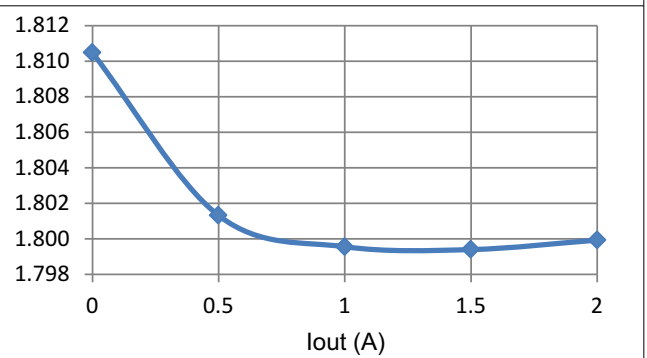
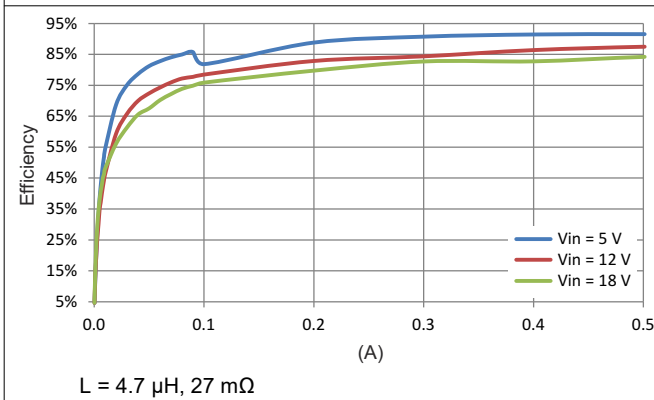
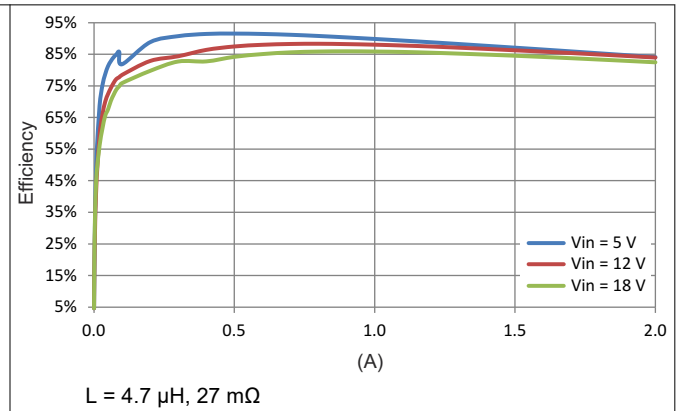
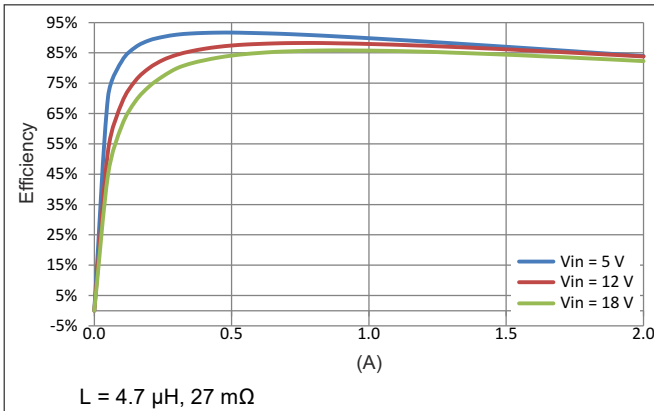


6-6. Current Limit  $V_{IN} = 12\text{ V}$ ,  $f_{SW} = 500\text{ KHz}$



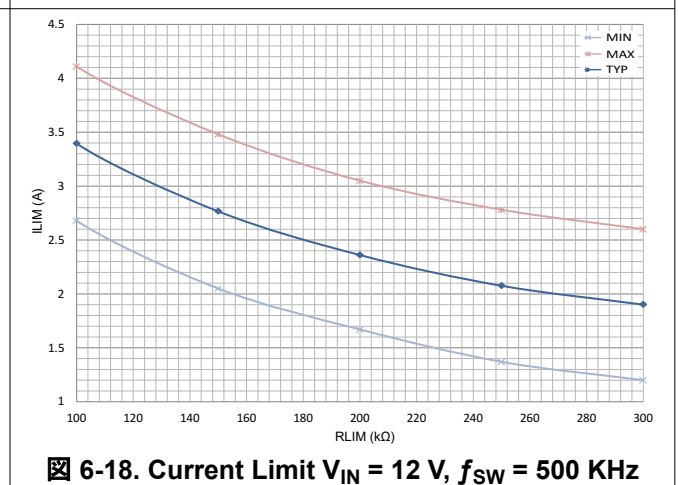
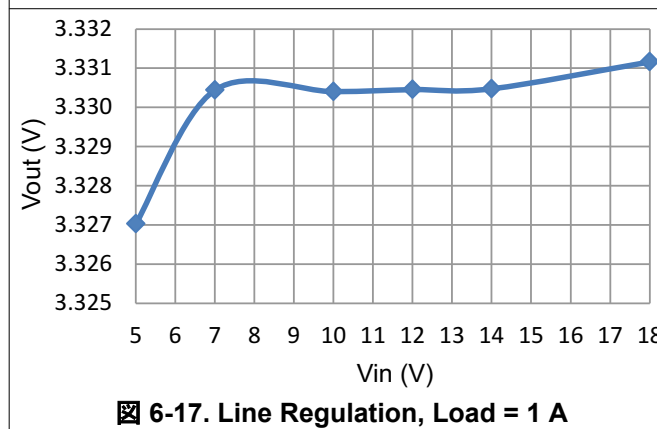
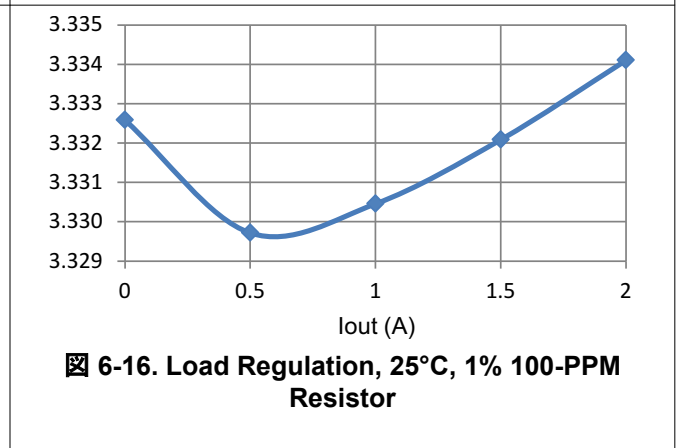
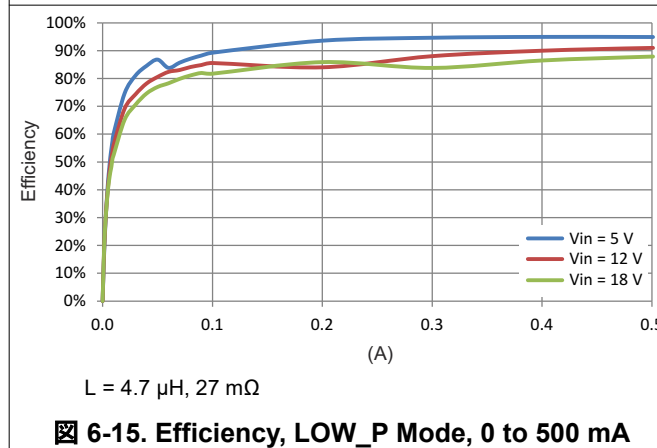
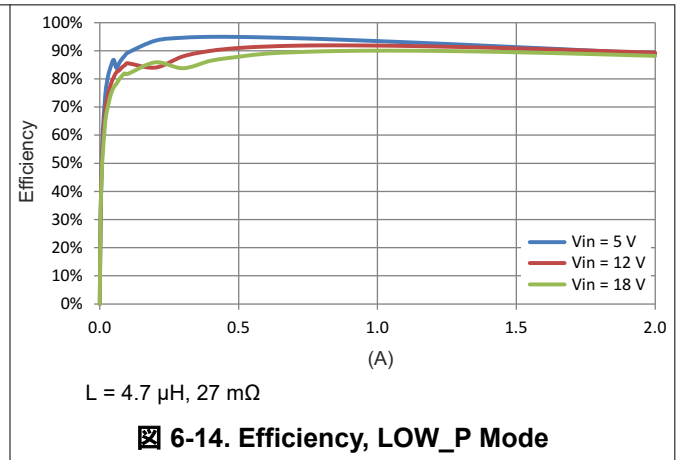
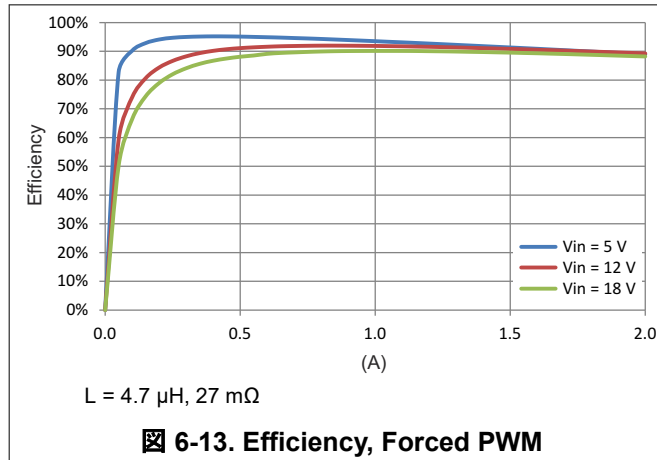
## 6.7 Typical Characteristics for Buck 2

$T_A = 25^\circ\text{C}$ ,  $V_{IN} = 12\text{ V}$ ,  $V_O = 1.8\text{ V}$ ,  $L = 4.7\ \mu\text{H}$ ,  $C_O = 68\ \mu\text{F}$ ,  $f_{SW} = 500\text{ Hz}$  (unless otherwise noted)



## 6.8 Typical Characteristics for Buck 3

$T_A = 25^\circ\text{C}$ ,  $V_{IN} = 12\text{ V}$ ,  $V_O = 3.3\text{ V}$ ,  $L = 4.7\ \mu\text{H}$ ,  $C_O = 68\ \mu\text{F}$ ,  $f_{SW} = 500\text{ Hz}$  (unless otherwise noted)



## 7 Detailed Description

### 7.1 Overview

TPS65251-x is a power management IC with three step-down buck converters. Both high-side and low-side MOSFETs are integrated to provide fully synchronous conversion with higher efficiency. TPS65251-x can support 4.5- to 18-V input supply, high load current, 300-kHz to 2.2-MHz clocking. The buck converters have an optional PSM mode, which can improve power dissipation during light loads. Alternatively, the device implements a constant frequency mode by connecting the LOW\_P pin to ground. The wide switching frequency of 300 kHz to 2.2 MHz allows for efficiency and size optimization. The switching frequency is adjustable by selecting a resistor to ground on the ROSC pin. The SYNC pin also provides a means to synchronize the power converter to an external signal. Input ripple is reduced by 180° out-of-phase operation between Buck 1 and Buck 2. Buck 3 operates in phase with Buck 2.

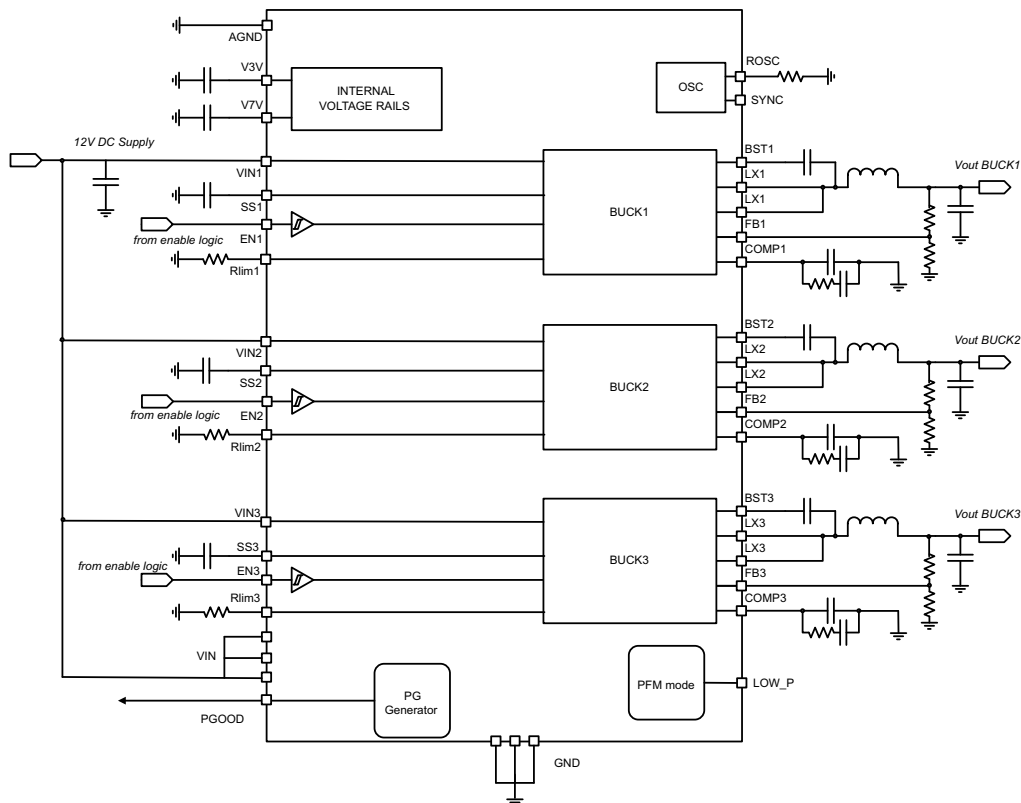
All three buck converters have peak current mode control which simplifies external frequency compensation. A traditional type II compensation network can stabilize the system and achieve fast transient response. Moreover, an optional capacitor in parallel with the upper resistor of the feedback divider provides one more zero and makes the crossover frequency over 100 kHz.

Each buck converter has an individual current limit, which can be set up by a resistor to ground from the RLIM pin. The adjustable current limiting enables high-efficiency design with smaller and less expensive inductors.

The device has two built-in LDO regulators. During a standby mode, the 3.3-V LDO and the 6.5-V LDO can be used to drive MCU and other active loads. By this, the system is able to turn off the three buck converters and improve the standby efficiency.


The device has a power-good comparator monitoring the output voltage. Each converter has its own soft-start and enable pins, which provide independent control and programmable soft-start.

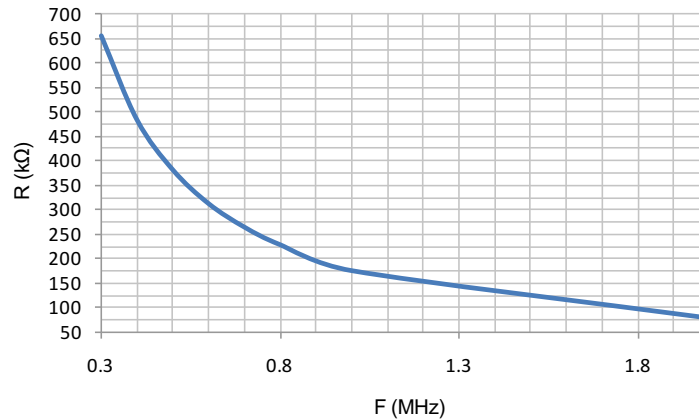
### 7.2 Functional Block Diagram



## 7.3 Feature Description

### 7.3.1 Adjustable Switching Frequency

To select the internal switching frequency, connect a resistor from RO<sub>SC</sub> to ground.  7-1 shows the required resistance for a given switching frequency.



 7-1. RO<sub>SC</sub> vs Switching Frequency

$$R_{\text{OSC}} (\text{k}\Omega) = 174 \times f (\text{MHz})^{-1.122} \quad (1)$$

For operation at 800 kHz, a 230-kΩ resistor is required.

### 7.3.2 Synchronization

The status of the SYNC pin is ignored during start-up and the TPS65251's control only synchronizes to an external signal after the PGOOD signal is asserted. The status of the SYNC pin is ignored during start-up and the TPS65251 only synchronizes to an external clock if the PGOOD signal is asserted. When synchronization is applied, the PWM oscillator frequency must be lower than the sync pulse frequency to allow the external signal trumping the oscillator pulse reliably. When synchronization is not applied, the SYNC pin should be connected to ground.


### 7.3.3 Out-of-Phase Operation

Buck 1 has a low conduction resistance compared to Buck 2 and 3. Normally Buck 1 is used to drive higher system loads. Buck 2 and 3 are used to drive some peripheral loads like I/O and line drivers. The combination of Buck 2's and Buck 3's loads may be on par with Buck 1's load. To reduce input ripple current, Buck 2 operates in phase with Buck 3; Buck 1 and Buck 2 operate 180° out-of-phase. This enables the system, having less input ripple, to lower component cost, save board space, and reduce EMI.

### 7.3.4 Delayed Start-Up

If a delayed start-up is required on any of the buck converters, fit a ceramic capacitor to the EN<sub>x</sub> pins. The delay added is approximately 1.67 ms per nF connected to the pin. Note that the EN pins have a weak 1-μA pull-up to the 3V3 rail.

### 7.3.5 Soft-Start Time

The device has an internal pullup current source of 5 μA that charges an external slow-start capacitor to implement a slow-start time.  2 shows how to select a slow-start capacitor based on an expected slow-start time. The voltage reference (V<sub>REF</sub>) is 0.8 V and the slow-start charge current (I<sub>SS</sub>) is 5 μA. The soft-start circuit requires 1 nF per 200 μs to be connected at the SS pin. A 1-ms soft-start time is implemented for all converters fitting 4.7 nF to the relevant pins.

$$t_{SS} \text{ (ms)} = V_{REF} \text{ (V)} \times \left( \frac{C_{SS} \text{ (nF)}}{I_{SS} \text{ (\mu A)}} \right) \quad (2)$$

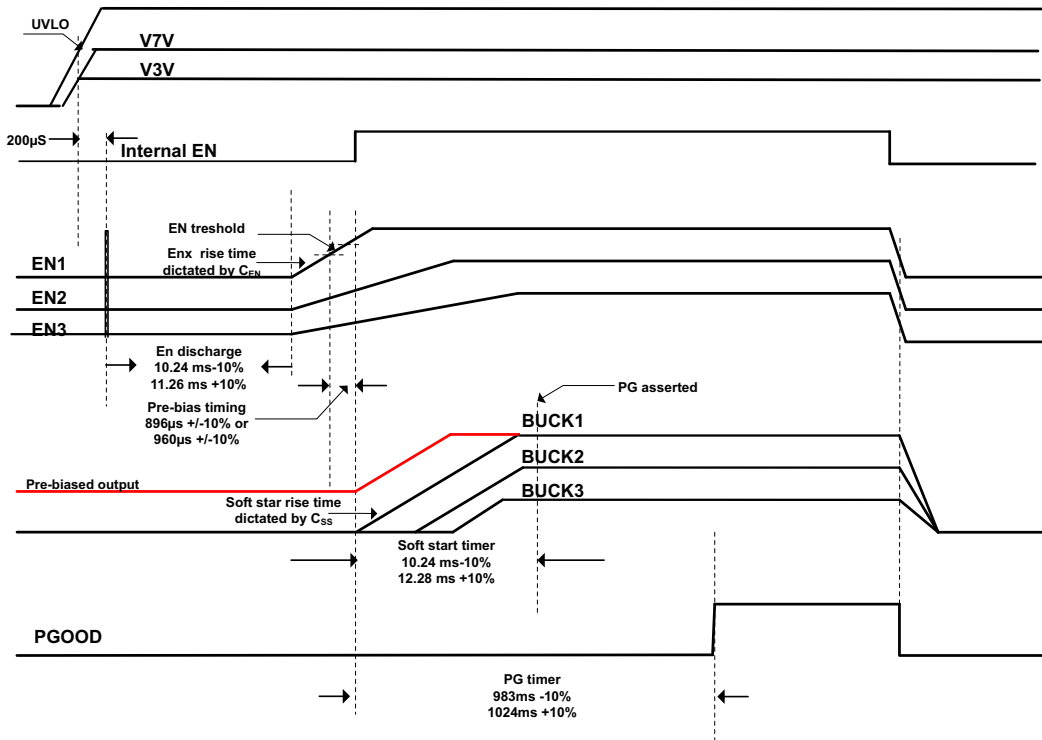


Fig 7-2. TPS65251-x Timing Diagram

### 7.3.6 Adjusting the Output Voltage

The output voltage is set with a resistor divider from the output node to the FB pin. TI recommends to use 1% tolerance or better divider resistors. To improve efficiency at light load, start with 40.2 kΩ for the R1 resistor and use 式 3 to calculate R2.

$$R2 = R1 \times \left( \frac{0.8 \text{ V}}{V_O - 0.8 \text{ V}} \right) \quad (3)$$

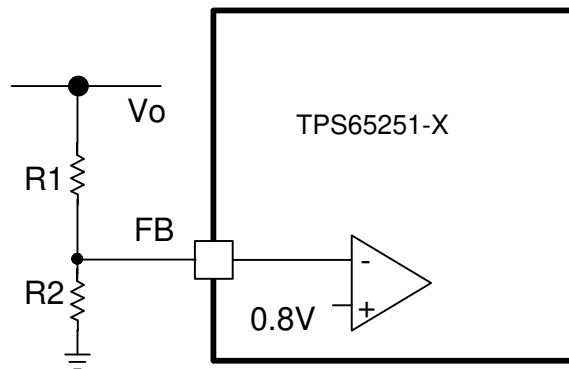


Fig 7-3. Voltage Divider Circuit

### 7.3.7 Input Capacitor

Use 10-μF X7R/X5R ceramic capacitors at the input of the converter inputs. Connect these capacitors as close as physically possible to the input pins of the converters.

### 7.3.8 Bootstrap Capacitor

The device has three integrated boot regulators and requires a small ceramic capacitor between the BST and LX pin to provide the gate drive voltage for the high-side MOSFET. The value of the ceramic capacitor should be 0.047  $\mu$ F. TI recommends a ceramic capacitor with an X7R or X5R grade dielectric because of the stable characteristics over temperature and voltage.

### 7.3.9 Error Amplifier

The device has a transconductance error amplifier. The frequency compensation network is connected between the COMP pin and ground.

### 7.3.10 Slope Compensation

The device has a built-in slope compensation ramp. The slope compensation can prevent subharmonic oscillations in peak current mode control.

### 7.3.11 Power Good

The PGOOD pin is an open-drain output. The PGOOD pin is pulled low when any buck converter is pulled below 85% of the nominal output voltage. TI recommends to use a pullup resistor from the PGOOD to the output of Buck 1. The PGOOD is pulled up when all three buck converters' outputs are more than 90% of its nominal output voltage.

The reset time of the PGOOD pin varies according to the part:

- TPS65251-1 is 1 s.
- TPS65251-2 is 32 ms.
- TPS65251-3 is 256 ms.

The polarity of the PGOOD pin is active high.

### 7.3.12 3.3-V and 6.5-V LDO Regulators

The following ceramic capacitor (X7R/X5R) should be connected as close as possible to the described pins:

- 10  $\mu$ F for V7V pin 28
- 3.3  $\mu$ F for V3V pin 29

### 7.3.13 Current Limit Protection

All converters operate in hiccup mode: After an overcurrent event lasting more than 10 ms is sensed in any of the converters, all the converters shut down for 10 ms, then the start-up sequencing is retried. If the overload has been removed, the converter ramps up and operates normally. If this is not the case, the converter senses another overcurrent event and shuts down again, repeating the cycle (hiccup) until the failure is cleared.

If an overload condition lasts for <10 ms, only the relevant affected converter goes into and out of under voltage and no global hiccup mode occurs. The converter is protected by the cycle-by-cycle current limit during that time.

### 7.3.14 Overvoltage Transient Protection (OVP)

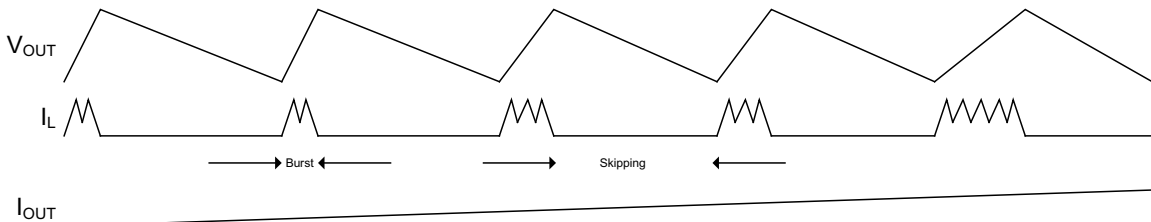
The device incorporates an OVP circuit to minimize voltage overshoot. The OVP feature minimizes the output overshoot by implementing a circuit to compare the FB pin voltage to OVP threshold, which is typical 106% of the internal voltage reference. If the FB pin voltage is greater than the OVP threshold, the high-side MOSFET is disabled preventing current from flowing to the output and minimizing output overshoot. When the FB voltage drops below the lower OVP threshold, which is typical 104%, the high-side MOSFET is allowed to turn on the next clock cycle.

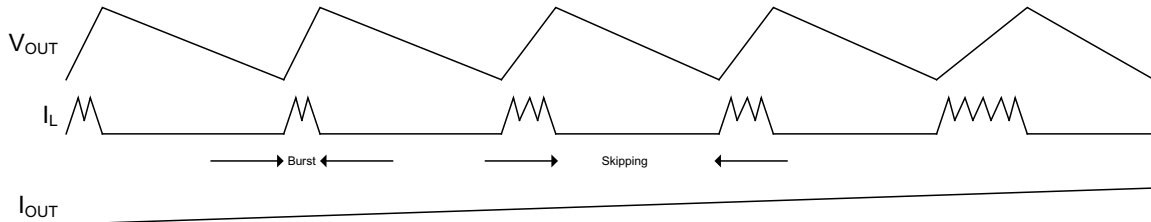
### 7.3.15 Thermal Shutdown

The device implements an internal thermal shutdown to protect itself if the junction temperature exceeds 160°C. The thermal shutdown forces the device to stop switching when the junction temperature exceeds thermal trip threshold. After the die temperature decreases below 140°C, the device reinitiates the power-up sequence. The thermal shutdown hysteresis is 20°C.

## 7.4 Device Functional Modes

### 7.4.1 Low-Power/Pulse Skipping Operation

When a synchronous buck converter operates at light load or standby conditions, the switching losses are the dominant source of power losses. Under these load conditions, TPS65251-x uses a pulse skipping modulation technique to reduce the switching losses by keeping the power transistors in the off-state for several switching cycles, while maintaining a regulated output voltage.  Figure 7-4 shows the output voltage and load plus the inductor current.



**Figure 7-4. Low Power/Pulse Skipping**

During the burst mode, the converter continuously charges up the output capacitor until the output voltage reaches a certain limit threshold. The operation of the converter in this interval is equivalent to the peak inductor current mode control. In each switch period, the main switch is turned on until the inductor current reaches the peak current limit threshold. As the load increases, the number of pulses increases to make sure that the output voltage stays within regulation limits. When the load is very light, the low-power controller has a zero crossing detector to allow the low-side MOSFET to operate even in light load conditions. The transistor is not disabled at light loads. A zero crossing detection circuit disables it when inductor current reverses. During the whole process, the body diode does not conduct, but is used as blocking diode only.

During the skipping interval, the upper and lower transistors are turned off and the converter stays in idle mode. The output capacitors are discharged by the load current until the moment when the output voltage drops to a low threshold.

The choice of output filter influences the performance of the low-power circuit. The maximum ripple during low-power mode can be calculated as:

$$V_{\text{OUT\_RIPPLE}} = \frac{K_{\text{RIP}} T_{\text{S}}}{C_{\text{OUT}}} \quad (4)$$

where

- $K_{\text{RIP}}$  is 1.4 for Buck 1.
- $K_{\text{RIP}}$  is 0.7 for Buck 2 and Buck 3.

$T_{\text{S}}$  can be calculated as:

$$T_{\text{S}} = \frac{0.35}{\left[ \left( \frac{V_{\text{IN}} - V_{\text{OUT}}}{L} \right) \frac{V_{\text{OUT}}}{V_{\text{IN}}} \right]} \quad (5)$$

## 8 Application and Implementation

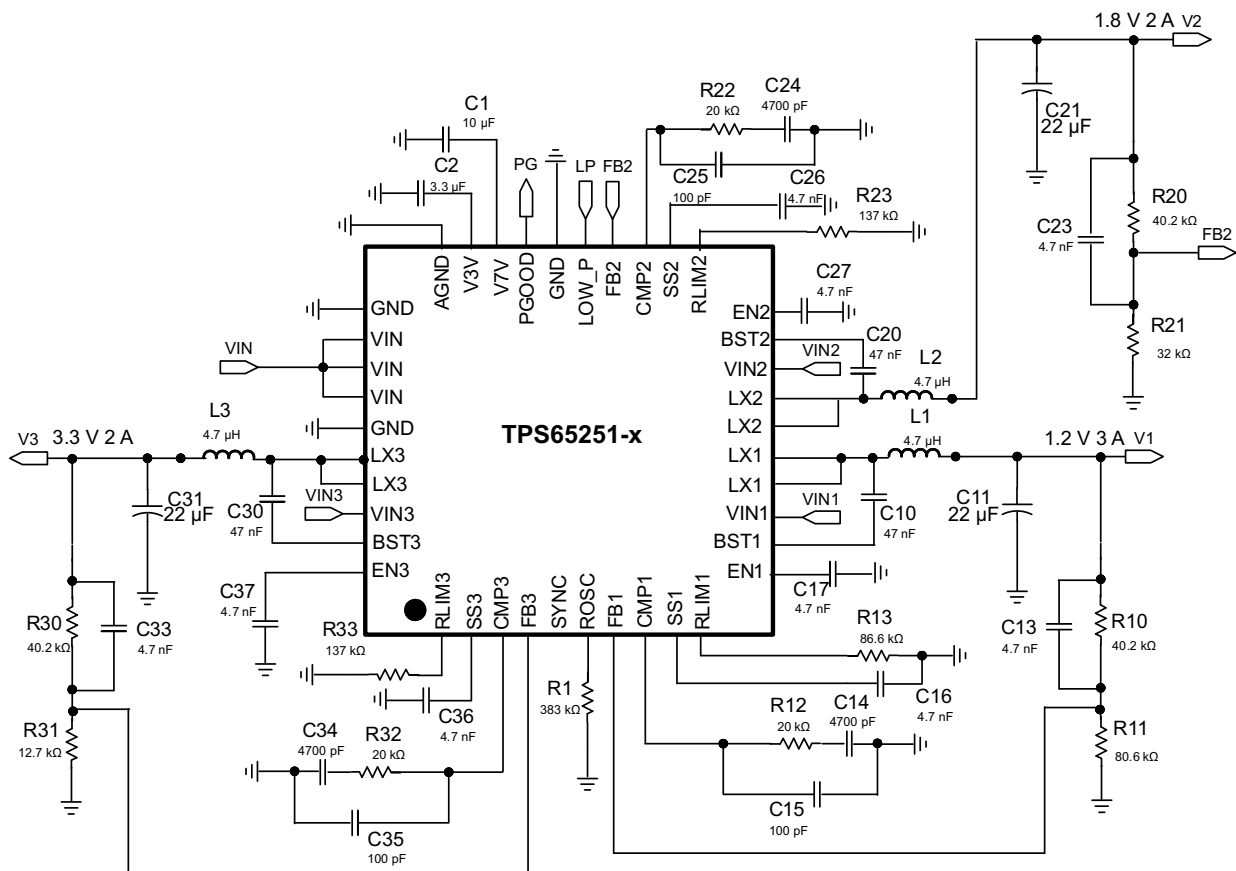
### Note

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### 8.1 Application Information

The device is triple synchronous step down dc/dc converter. It is typically used to convert a higher dc voltage to lower dc voltages with continuous available output current of 3 A/2 A/2 A. The following design procedure can be used to select component values for the TPS65251-x.

### 8.2 Typical Application



A. VIN pins require local decoupling capacitors.

**8-1. Typical Application Circuit**

#### 8.2.1 Design Requirements

| DESIGN PARAMETERS                         | VALUE                   |
|---|-------------------------|
| Output voltage                            | 1.2 V                   |
| Transient response 0.5-A to 2-A load step | 120 mV                  |
| Maximum output current                    | 3 A                     |
| Input voltage                             | 12 V nom, 9.6 to 14.4 V |
| Output voltage ripple                     | <30 mV p-p              |

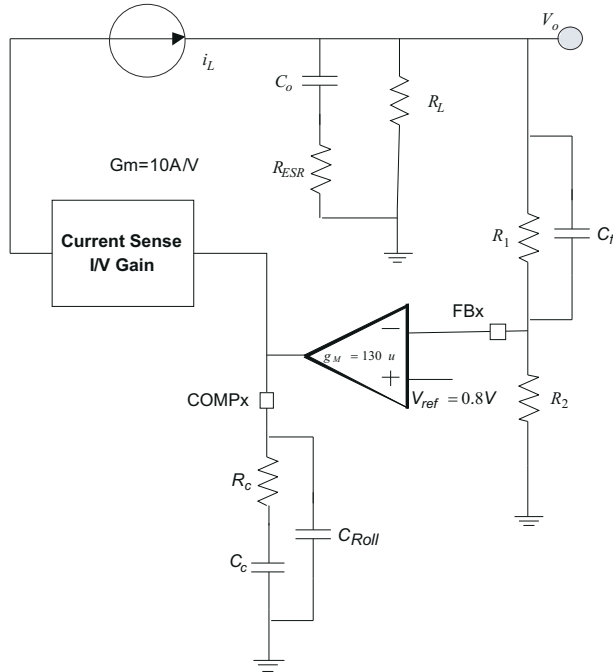


| DESIGN PARAMETERS   | VALUE   |
|---------------------|---------|
| Switching frequency | 500 kHz |

## 8.2.2 Detailed Design Procedure

### 8.2.2.1 Loop Compensation Circuit

A typical compensation circuit could be type II ( $R_c$  and  $C_c$ ) to have a phase margin between  $60^\circ$  and  $90^\circ$ , or type III ( $R_c$ ,  $C_c$  and  $C_{ff}$ ) to improve the converter transient response.  $C_{Roll}$  adds a high frequency pole to attenuate high-frequency noise when needed. It may also prevent noise coupling from other rails if there is possibility of cross coupling in between rails when layout is very compact.



**8-2. Loop Compensation**

To calculate the external compensation components use [表 8-1](#):

**表 8-1. Design Guideline for the Loop Compensation**

|   | TYPE II CIRCUIT  | TYPE III CIRCUIT  |
|---|--|---|
| Select switching frequency that is appropriate for application depending on L, C sizes, output ripple, EMI concerns and etc. Switching frequencies between 500 kHz and 1 MHz give best trade off between performance and cost. When using smaller L and Cs, switching frequency can be increased. To optimize efficiency, switching frequency can be lowered. |  | Type III circuit recommended for switching frequencies higher than 500 kHz. |
| Select cross over frequency ( $f_c$ ) to be less than 1/5 to 1/10 of switching frequency.   | Suggested $f_c = f_s/10$   | Suggested $f_c = f_s/10$  |
| Set and calculate $R_c$ .   | $R_c = \frac{2\pi \times f_c \times V_o \times C_o}{g_M \times V_{ref} \times g_{m_{ps}}} \quad (6)$ | $R_c = \frac{2\pi \times f_c \times C_o}{g_M \times g_{m_{ps}}} \quad (7)$  |
| Calculate $C_c$ by placing a compensation zero at or before the converter dominant pole<br>$f_p = \frac{1}{C_o \times R_L \times 2\pi}$   | $C_c = \frac{R_L \times C_o}{R_c} \quad (8)$   | $C_c = \frac{R_L \times C_o}{R_c} \quad (10)$                               |

表 8-1. Design Guideline for the Loop Compensation (continued)

|   | TYPE II CIRCUIT  | TYPE III CIRCUIT  |
|---|--|---|
| Add $C_{Roll}$ if needed to remove large signal coupling to high impedance COMP node. Make sure that<br>$f_{p_{Roll}} = \frac{1}{2 \times \pi \times R_C \times C_{Roll}} \quad (11)$ is at least twice the cross over frequency. | $C_{Roll} = \frac{Re_{sr} \times C_O}{R_C} \quad (12)$ | $C_{Roll} = \frac{Re_{sr} \times C_O}{R_C} \quad (13)$                    |
| Calculate $C_{ff}$ compensation zero at low frequency to boost the phase margin at the crossover frequency. Make sure that the zero frequency ( $f_{z_{ff}}$ ) is smaller than soft-start equivalent frequency ( $1/T_{ss}$ ).    | NA   | $C_{ff} = \frac{1}{2 \times \pi \times f_{z_{ff}} \times R_1} \quad (14)$ |

### 8.2.2.2 Selecting the Switching Frequency

The first step is to decide on a switching frequency for the regulator. Typically, you will want to choose the highest switching frequency possible since this will produce the smallest solution size. The high switching frequency allows for lower valued inductors and smaller output capacitors compared to a power supply that switches at a lower frequency. However, the highest switching frequency causes extra switching losses, which hurt the converter's performance. The converter is capable of running from 300 kHz to 2.2 MHz. Unless a small solution size is an ultimate goal, a moderate switching frequency of 500 kHz is selected to achieve both a small solution size and a high efficiency operation. Using [Figure 7-1](#),  $R_1$  is determined to be 383 k $\Omega$ .

### 8.2.2.3 Output Inductor Selection

To calculate the value of the output inductor, use [Equation 15](#).  $K_{IND}$  is a coefficient that represents the amount of inductor ripple current relative to the maximum output current. In general,  $K_{IND}$  is normally from 0.1 to 0.3 for the majority of applications.

For this design example, use  $K_{IND} = 0.2$  and the inductor value is calculated to be 3.6  $\mu$ H. For this design, a nearest standard value was chosen: 4.7  $\mu$ H. For the output filter inductor, it is important that the RMS current and saturation current ratings not be exceeded. The RMS and peak inductor current can be found from [Equation 16](#) and [Equation 17](#).

$$L_O = \frac{V_{in} - V_{out}}{I_o \times K_{ind}} \times \frac{V_{out}}{V_{in} \times f_{sw}} \quad (15)$$

$$I_{ripple} = \frac{V_{in} - V_{out}}{L_O} \times \frac{V_{out}}{V_{in} \times f_{sw}} \quad (16)$$

$$I_{Lrms} = \sqrt{I_o^2 + \frac{1}{12} \times \left( \frac{V_o \times (V_{inmax} - V_o)}{V_{inmax} \times L_O \times f_{sw}} \right)^2} \quad (17)$$

$$I_{Lpeak} = I_{out} + \frac{I_{ripple}}{2} \quad (18)$$

### 8.2.2.4 Output Capacitor

There are two primary considerations for selecting the value of the output capacitor. The output capacitors are selected to meet load transient and output ripple's requirements.

[Equation 19](#) gives the minimum output capacitance to meet the transient specification. For this example,  $L_O = 4.7 \mu$ H,  $\Delta I_{OUT} = 1.5 \text{ A} - 0.75 \text{ A} = 0.75 \text{ A}$  and  $\Delta V_{OUT} = 120 \text{ mV}$ . Using these numbers gives a minimum capacitance of 18  $\mu$ F. A standard 22- $\mu$ F ceramic capacitor is chosen in the design.

$$C_o > \frac{\Delta I_{OUT}^2 \times L_o}{V_{out} \times \Delta V_{out}} \quad (19)$$

式 20 calculates the minimum output capacitance needed to meet the output voltage ripple specification. Where  $f_{sw}$  is the switching frequency,  $V_{RIPPLE}$  is the maximum allowable output voltage ripple, and  $I_{RIPPLE}$  is the inductor ripple current. In this case, the maximum output voltage ripple is 30 mV. From 式 16, the output current ripple is 0.46 A. From 式 20, the minimum output capacitance meeting the output voltage ripple requirement is 1.74  $\mu$ F.

$$C_o > \frac{1}{8 \times f_{sw}} \times \frac{1}{\frac{V_{ripple}}{I_{ripple}}} \quad (20)$$

Additional capacitance de-rating for aging, temperature and DC bias should influence this minimum value. For this example, one 22- $\mu$ F, 6.3-V X7R ceramic capacitor with 3 m $\Omega$  of ESR will be used.

### 8.2.2.5 Input Capacitor

A minimum 10- $\mu$ F X7R/X5R ceramic input capacitor is recommended to be added between VIN and GND. These capacitors should be connected as close as physically possible to the input pins of the converters as they handle the RMS ripple current shown in 式 21. For this example,  $I_{OUT} = 3$  A,  $V_{OUT} = 1.2$  V,  $V_{INmin} = 9.6$  V, from 式 21, the input capacitors must support a ripple current of 0.99 A RMS.

$$I_{cirms} = I_{out} \times \sqrt{\frac{V_{out}}{V_{inmin}} \times \frac{(V_{inmin} - V_{out})}{V_{inmin}}} \quad (21)$$

The input capacitance value determines the input ripple voltage of the regulator. The input voltage ripple can be calculated using 式 22. Using the design example values,  $I_{OUTmax} = 3$  A,  $C_{IN} = 10$   $\mu$ F,  $f_{SW} = 500$  kHz, yields an input voltage ripple of 150 mV.

$$\Delta V_{in} = \frac{I_{outmax} \times 0.25}{C_{in} \times f_{sw}} \quad (22)$$

### 8.2.2.6 Soft-Start Capacitor

The soft-start capacitor determines the minimum amount of time it will take for the output voltage to reach its nominal programmed value during power-up. This is useful if the output capacitance is very large and would require large amounts of current to quickly charge the capacitor to the output voltage level.

The soft-start capacitor value can be calculated using 式 23. In this example, the converter's soft-start time is 0.8 ms. In TPS65251-x,  $I_{ss}$  is 5  $\mu$ A and  $V_{ref}$  is 0.8 V. From 式 23, the soft-start capacitance is 5 nF. A standard 4.7-nF ceramic capacitor is chosen in this design. In this example, C16 is 4.7 nF

$$C_{ss}(nF) = \frac{T_{ss}(ms) \times I_{ss}(\mu A)}{V_{ref}(V)} \quad (23)$$

### 8.2.2.7 Bootstrap Capacitor Selection

A 0.047- $\mu$ F ceramic capacitor must be connected between the BST to LX pin for proper operation. It is recommended to use a ceramic capacitor with X5R or better grade dielectric. The capacitor should have 10-V or higher voltage rating.

### 8.2.2.8 Adjustable Current Limiting Resistor Selection

The converter uses the voltage drop on the high-side MOSFET to measure the inductor current. The overcurrent protection threshold can be optimized by changing the trip resistor. 图 6-6 governs the threshold of overcurrent

protection for Buck 1. When selecting a resistor, do not exceed the graph limits. In this example, the over current threshold is 3.2 A. In order to prevent a premature limit trip, the minimum line is used and the resistor is 86.6 kΩ.

When setting high-side current limit to large current values, ensure that the additional load immediately prior to an overcurrent condition will not cause the switching node voltage to exceed 20 V. Additionally, ensure during worst case operation, with all bucks loaded immediately prior to current limit, the maximum virtual junction temperature of the device does not exceed 125°C.

### 8.2.2.9 Output Voltage and Feedback Resistors Selection

For the example design, 40.2 kΩ was selected for R10. Vout is 1.2 V, Vref = 0.8 V. Using 式 24, R11 is calculated as 80.4 kΩ. A standard 80.6-kΩ resistor is chose in this design.

$$R11 = \frac{V_{out} - V_{ref}}{V_{ref}} \times R10 \quad (24)$$

### 8.2.2.10 Compensation

A type-II compensation circuit is adequate for the converter to have a phase margin between 60 and 90 degrees. The following equations show the procedure of designing a peak current mode control dc/dc converter.

The compensation design takes the following steps:

1. Set up the anticipated cross-over frequency. In this example, the anticipated cross-over frequency (fc) is 65 kHz. The power stage gain (gm<sub>PS</sub>) is 10 A/V and the GM amplifier gain (g<sub>M</sub>) is 130 μA/V.

$$R12 = \frac{2\pi \times f_c \times V_o \times C_o}{g_M \times V_{ref} \times g_{m_{ps}}} \quad (25)$$

2. Place compensation zero at low frequency to boost the phase margin at the crossover frequency. From the procedures above, the compensation network includes a 20-kΩ resistor (R12) and a 4700-pF capacitor (C1).
3. An additional pole can be added to attenuate high frequency noise.

From the procedures above, the compensation network includes a 20-kΩ resistor (R12) and a 4700-pF capacitor (C14).

### 8.2.2.11 3.3-V and 6.5-V LDO Regulators

The following ceramic capacitor (X7R/X5R) should be connected as close as possible to the described pins:

- 10 μF for V7V pin 28
- 3.3 μF to 10 μF for V3V pin 29

## 8.2.3 Application Curves

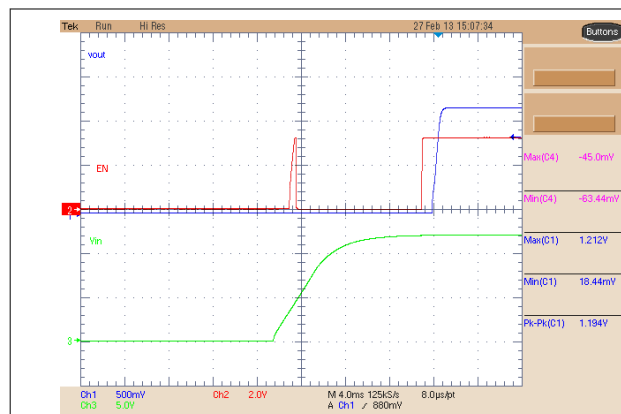


图 8-3. Buck 1 Start-Up (Ch3 = V<sub>IN</sub>)

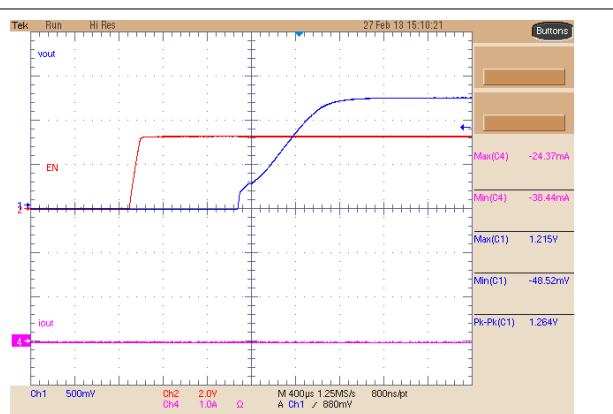
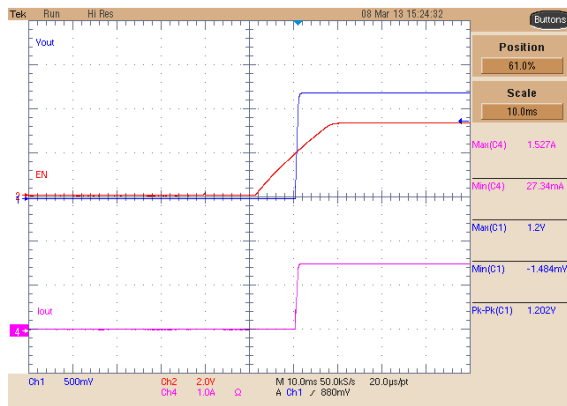
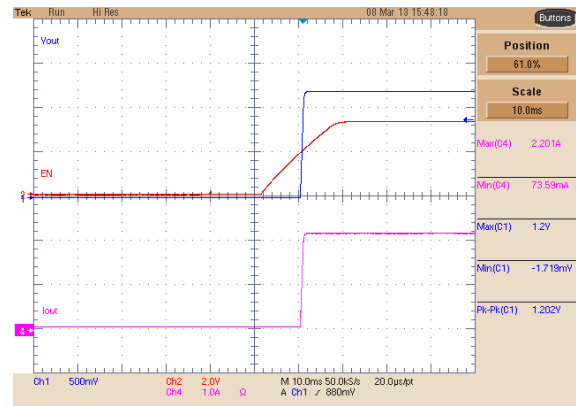


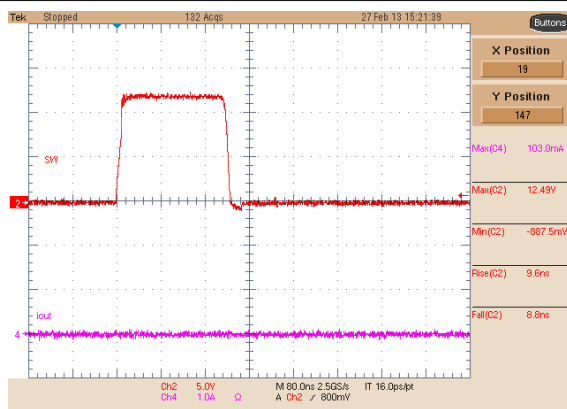
图 8-4. Buck 1 Soft-Start



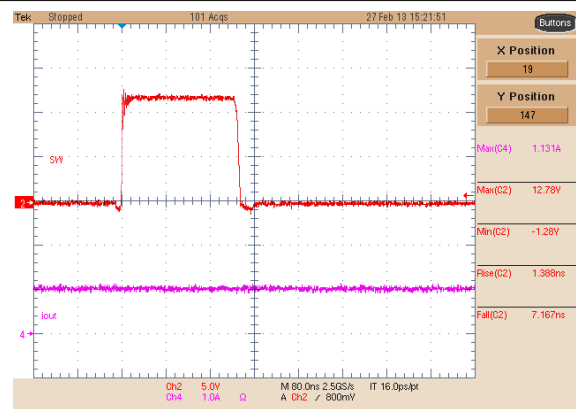
**8-5. Buck 1 Start-Up 1.5-A Resistive**



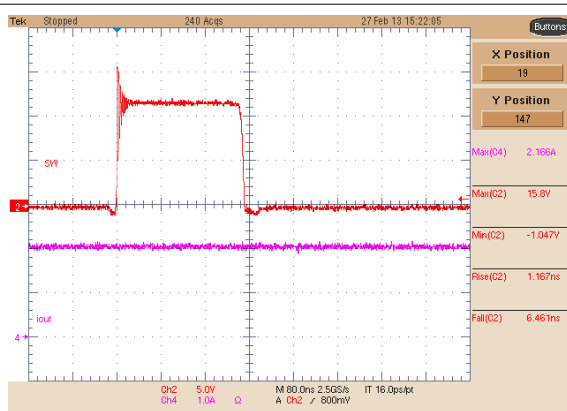
**8-6. Buck 1 Soft-Start 2-A Load**



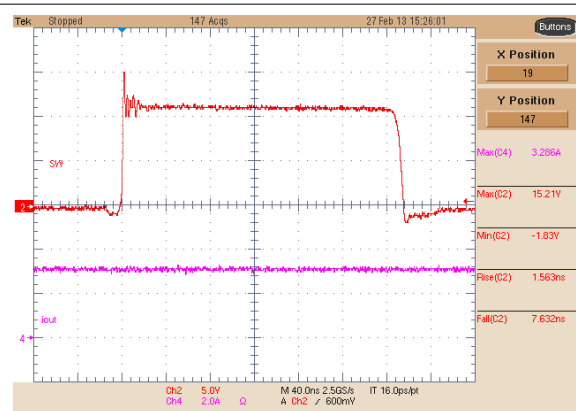
**8-7. Buck 1 Switching Node, No Load**



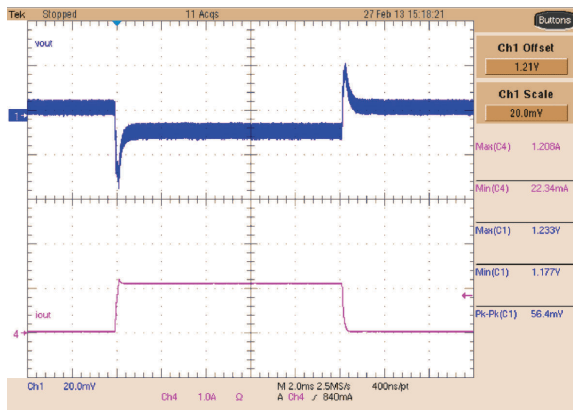
**8-8. Buck 1 Switching Node, 1-A Load**



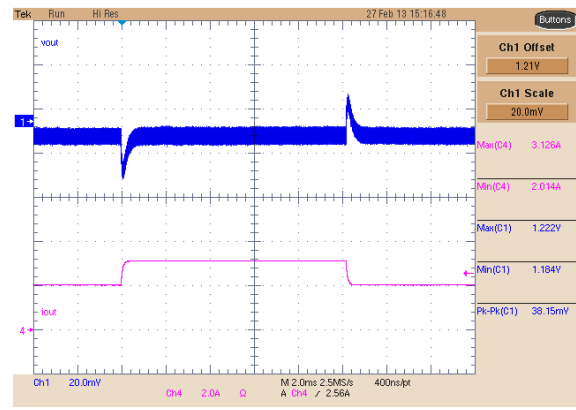
**8-9. Buck 1 Switching Node, 2-A Load**



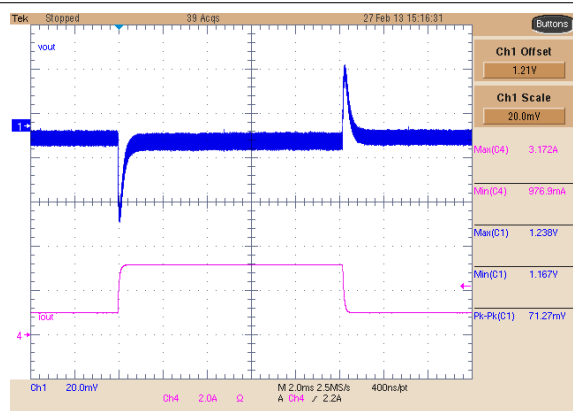
**8-10. Buck 1 Switching Node, 3-A Load**



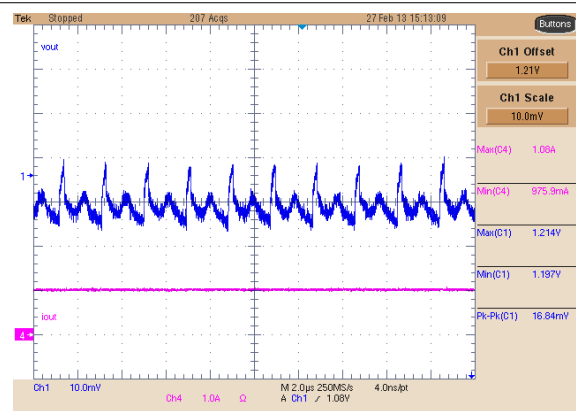
8-11. Buck 1 Dynamic Response, 0- to 1-A Step



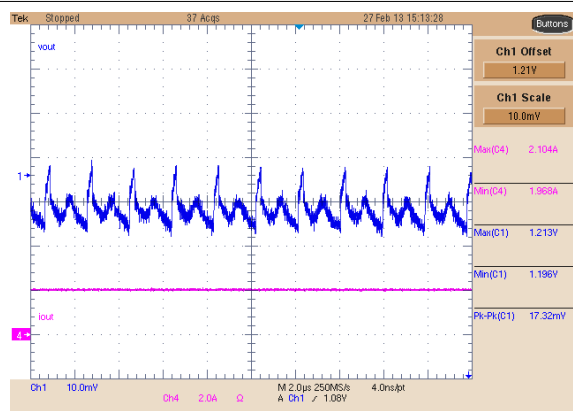
8-12. Buck 1 Dynamic Response, 2-A to 3-A Step



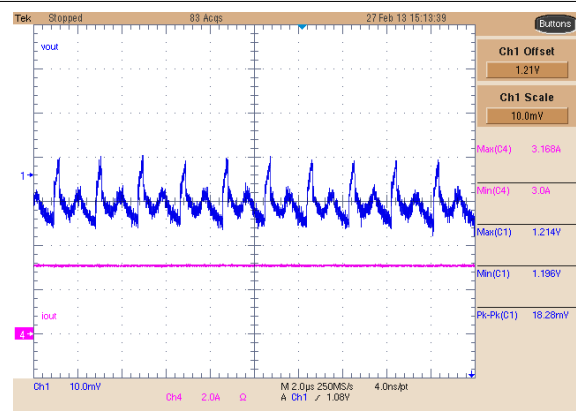
8-13. Buck 1 Dynamic Response, 1-A to 3-A Step



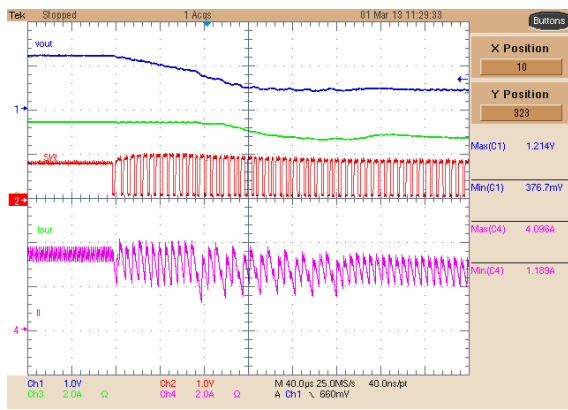
8-14. Buck 1 Ripple, 1-A Load



8-15. Buck 1 Ripple, 2-A Load

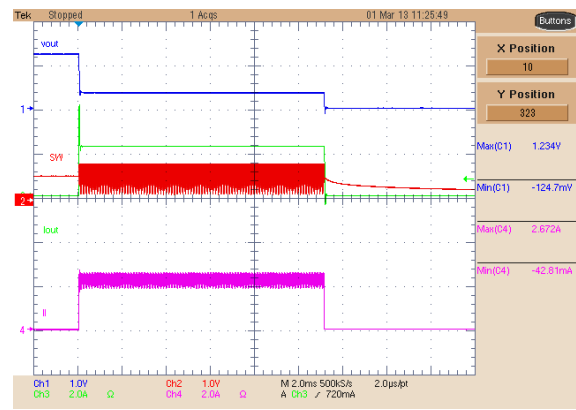


8-16. Buck 1 Ripple, 3-A Load



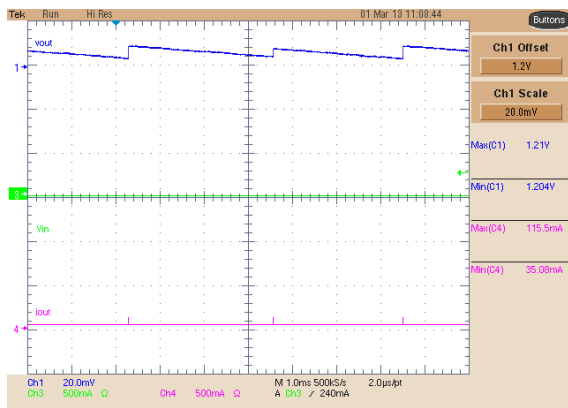
Ch1 =  $V_{OUT}$     Ch2 = COMP1    Ch3 =  $I_{OUT}$   
 Ch4 = Inductor

 **8-17. Buck 1 Current Limit Operation With Slow Rising Output Current, Trip at 4 A**

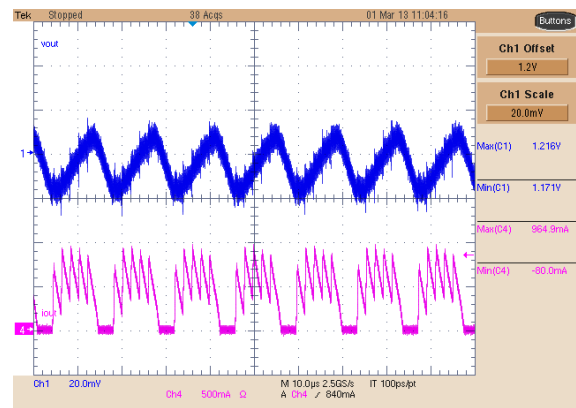


Ch1 =  $V_{OUT}$     Ch2 = COMP1    Ch3 =  $I_{OUT}$   
 Ch4 = Inductor

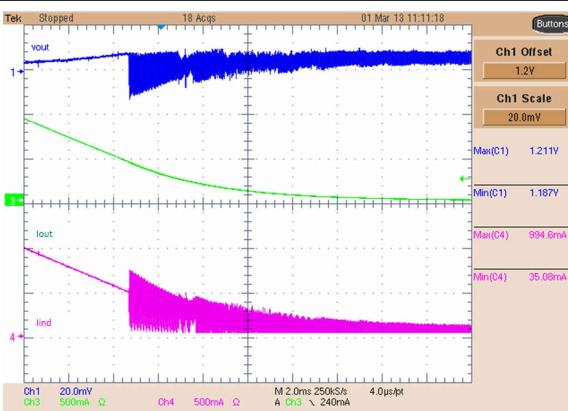
 **8-18. Buck 1 Current Limit Operation, Hiccup**



 **8-19. Buck 1 Low-Power Output, No Load**

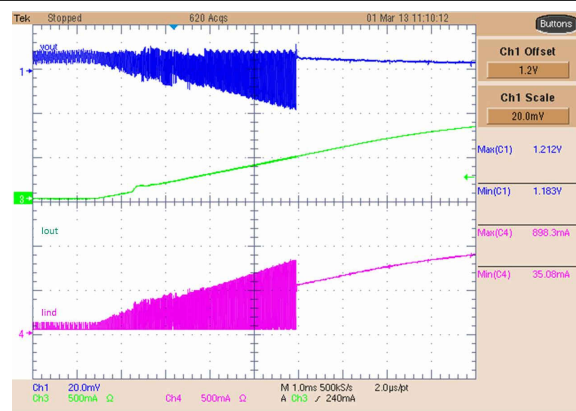


 **8-20. Buck 1 Low-Power Operation**



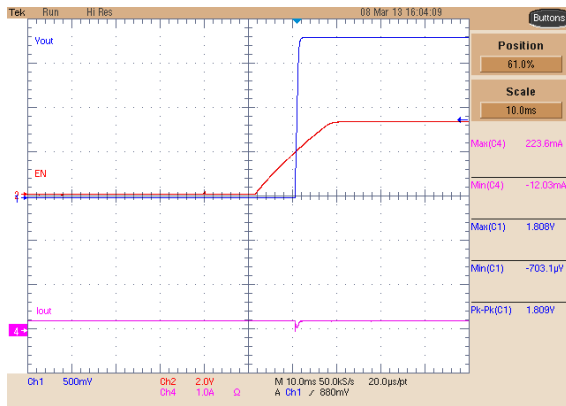
Ch1 =  $V_{OUT}$     Ch3 =  $I_{OUT}$     Ch4 = Inductor

 **8-21. Buck 1 PFM to PWM Transition**



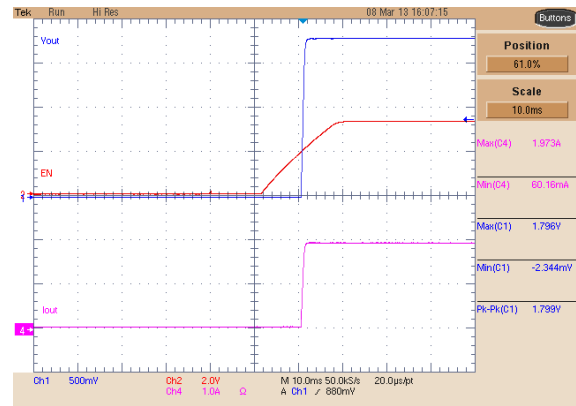
Ch1 =  $V_{OUT}$     Ch3 =  $I_{OUT}$     Ch4 = Inductor

 **8-22. Buck 1 PWM to PFM Transition**

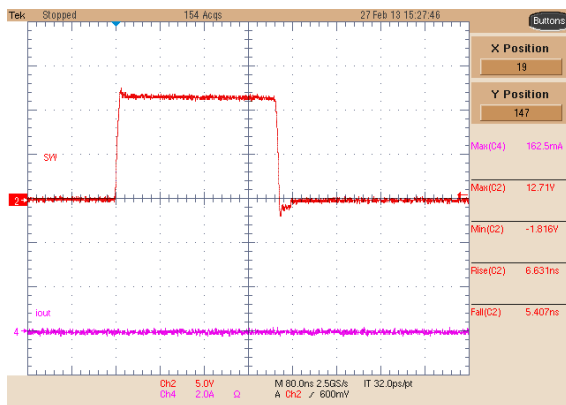


Ch3 =  $V_{IN}$

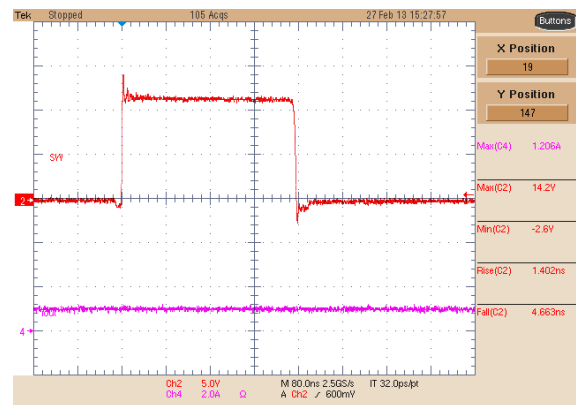
**8-23. Buck 2 Start-Up, No Load**



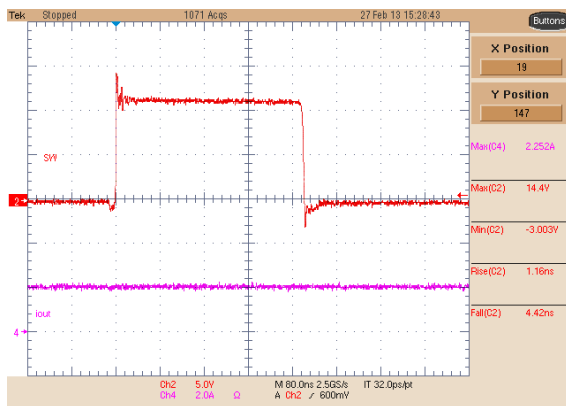
**8-24. Buck 2 Start-Up, 2-A Load**



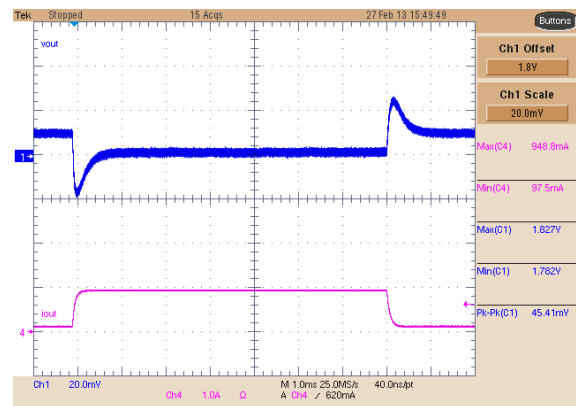
**8-25. Buck 2 Switching Node, No Load**



**8-26. Buck 2 Switching Node, 1-A Load**

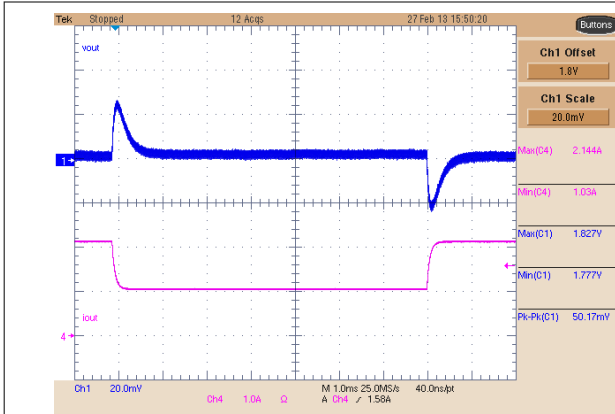


**8-27. Buck 2 Switching Node, 2-A Load**

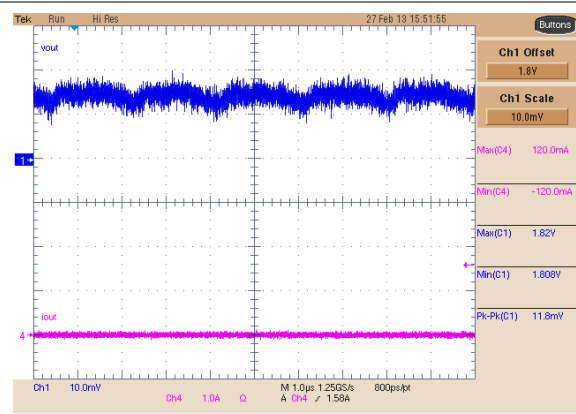


**8-28. Buck 2 Dynamic Response, 0-A to 1-A Step**

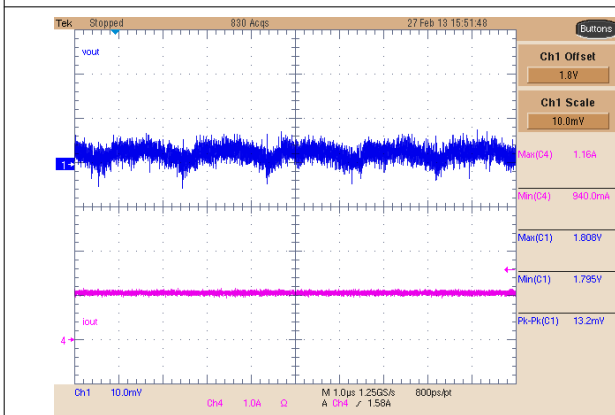




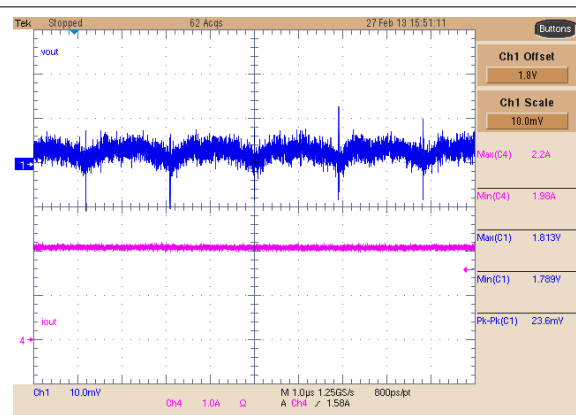

**8-29. Buck 2 Dynamic Response, 1-A to 2-A Step**



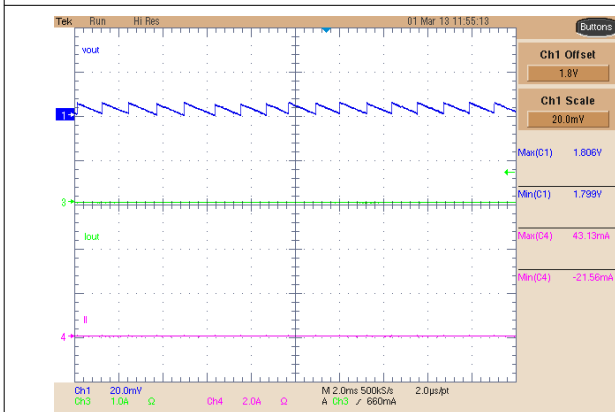

**8-30. Buck 2 Ripple, No Load**



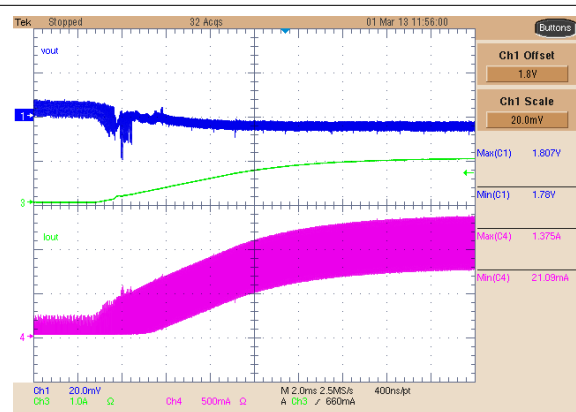

**8-31. Buck 2 Ripple, 1-A Load**




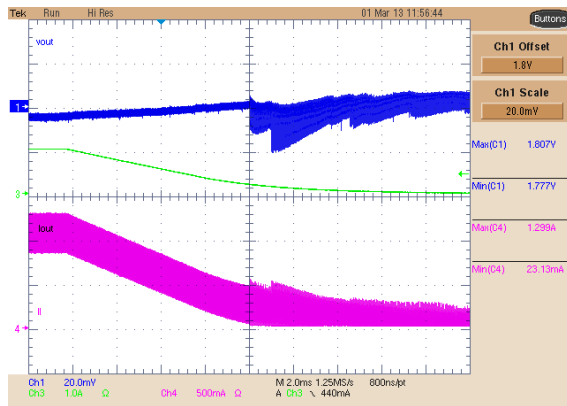

**8-32. Buck 2 Ripple, 3-A Load**



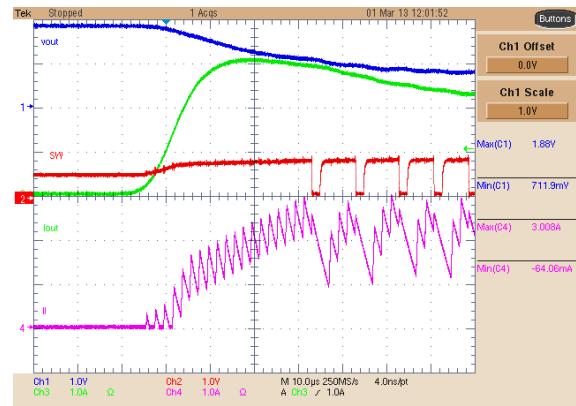

**8-33. Buck 2 Low-Power Output, No Load**



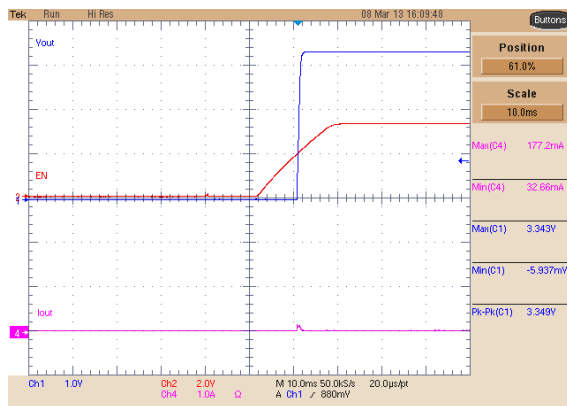
Ch1 =  $V_{OUT}$       Ch3 =  $I_{OUT}$       Ch4 = Inductor  

**8-34. Buck 2 PFM to PWM Transition**



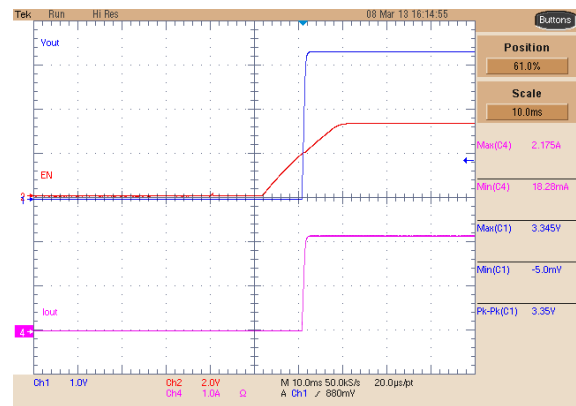
8-35. Buck 2 PWM to PFM Transition



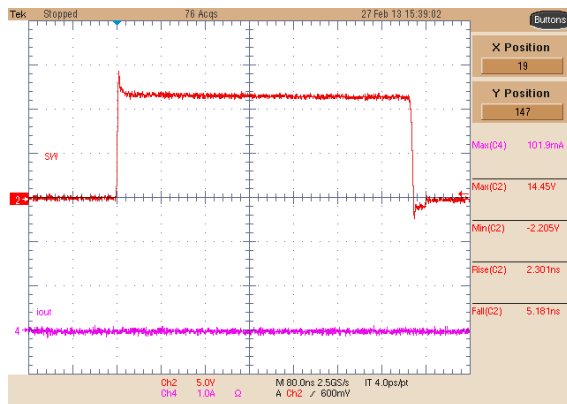
8-36. Buck 2 Current Limit Operation



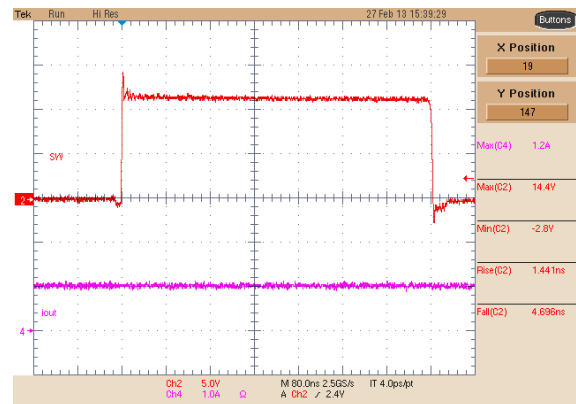
8-37. Buck 3 Start-Up



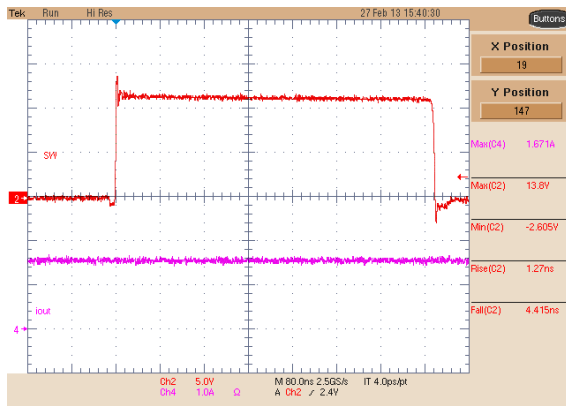
8-38. Buck 3 Soft-Start



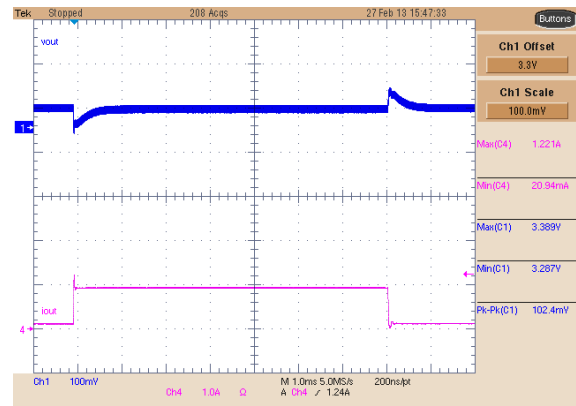
8-39. Buck 3 Switching Node, No Load



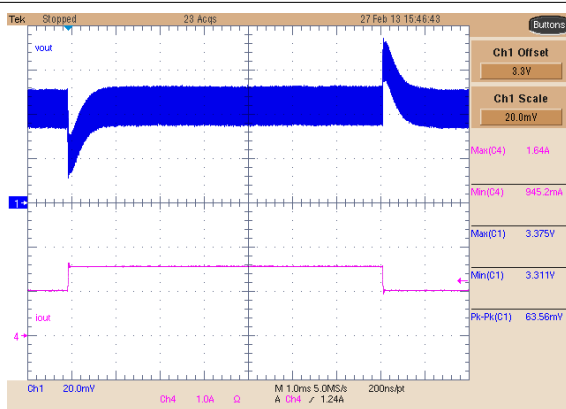
8-40. Buck 3 Switching Node, 1-A Load



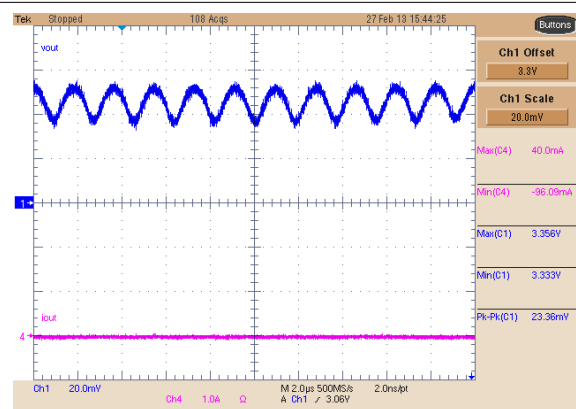
8-41. Buck 3 Switching Node, 1.5-A Load



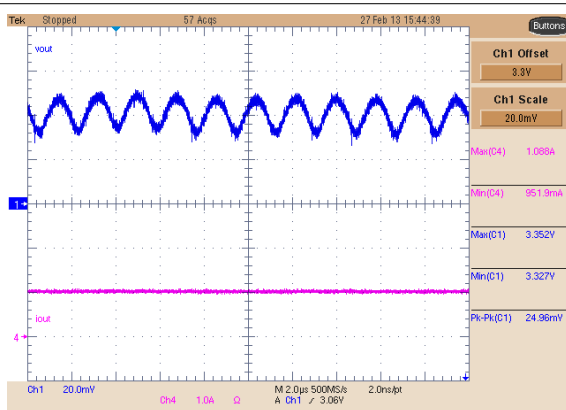
8-42. Buck 3 Dynamic Response, 0-A to 1-A Step



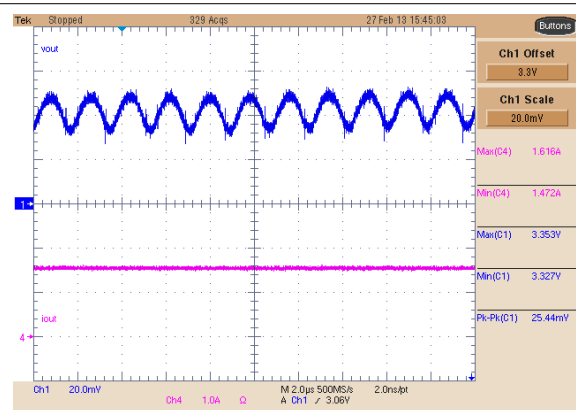
8-43. Buck 3 Dynamic Response, 1-A to 1.5-A Step



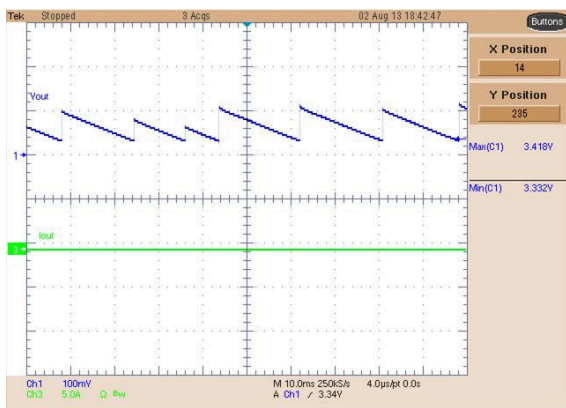
8-44. Buck 3 Ripple, No Load



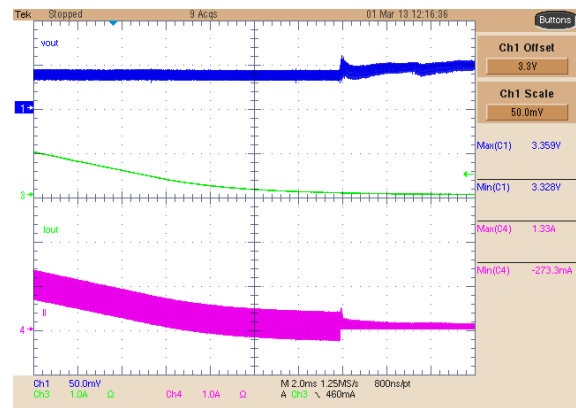
8-45. Buck 3 Ripple, 1-A Load



8-46. Buck 3 Ripple, 3-A Load

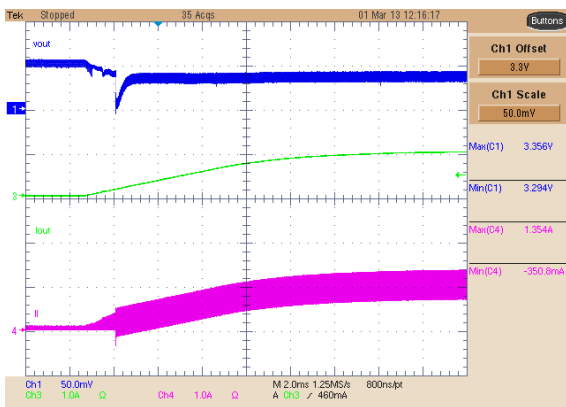


**8-47. Buck 3 Low-Power Output, No Load**



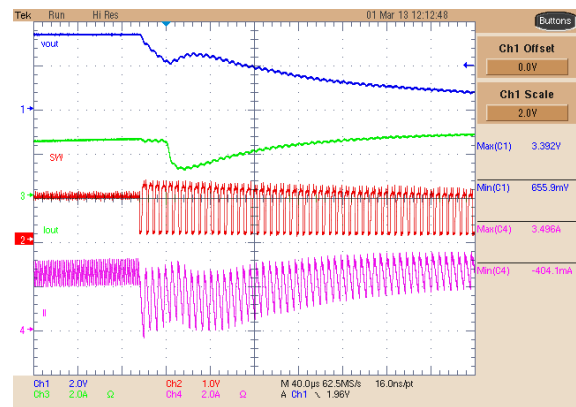
Ch1 =  $V_{OUT}$       Ch3 =  $I_{OUT}$       Ch4 = Inductor

**8-48. Buck 3 PFM to PWM Transition**



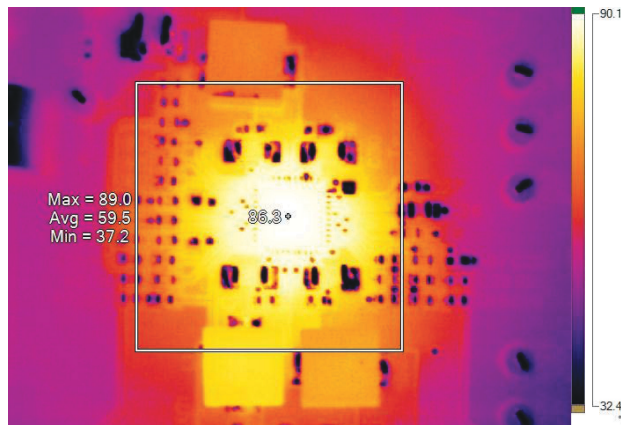
Ch1 =  $V_{OUT}$       Ch3 =  $I_{OUT}$       Ch4 = Inductor

**8-49. Buck 3 PWM to PFM Transition**



Ch1 =  $V_{OUT}$       Ch2 = COMP1      Ch3 =  $I_{OUT}$   
 Ch4 = Inductor

**8-50. Buck 3 Current Limit Operation**



**8-51. Temperature Profile,  $V_O = 1.2\text{ V}$ ,  $I_O = 3\text{ A}$ ,  $V_O = 1.8\text{ V}$ ,  $I_O = 2\text{ A}$ ,  $V_O = 3.3\text{ V}$ ,  $I_O = 2\text{ A}$ ,  $T_A = 28^\circ\text{C}$**

## 9 Power Supply Recommendations

The device is designed to operate from an input voltage supply range between 4.5 V and 18 V. This input power supply should be well regulated. If the input supply is located more than a few inches from the TPS65251-x converter, additional bulk capacitance may be required in addition to the ceramic bypass capacitors. An electrolytic capacitor with a value of 47  $\mu$ F is a typical choice.

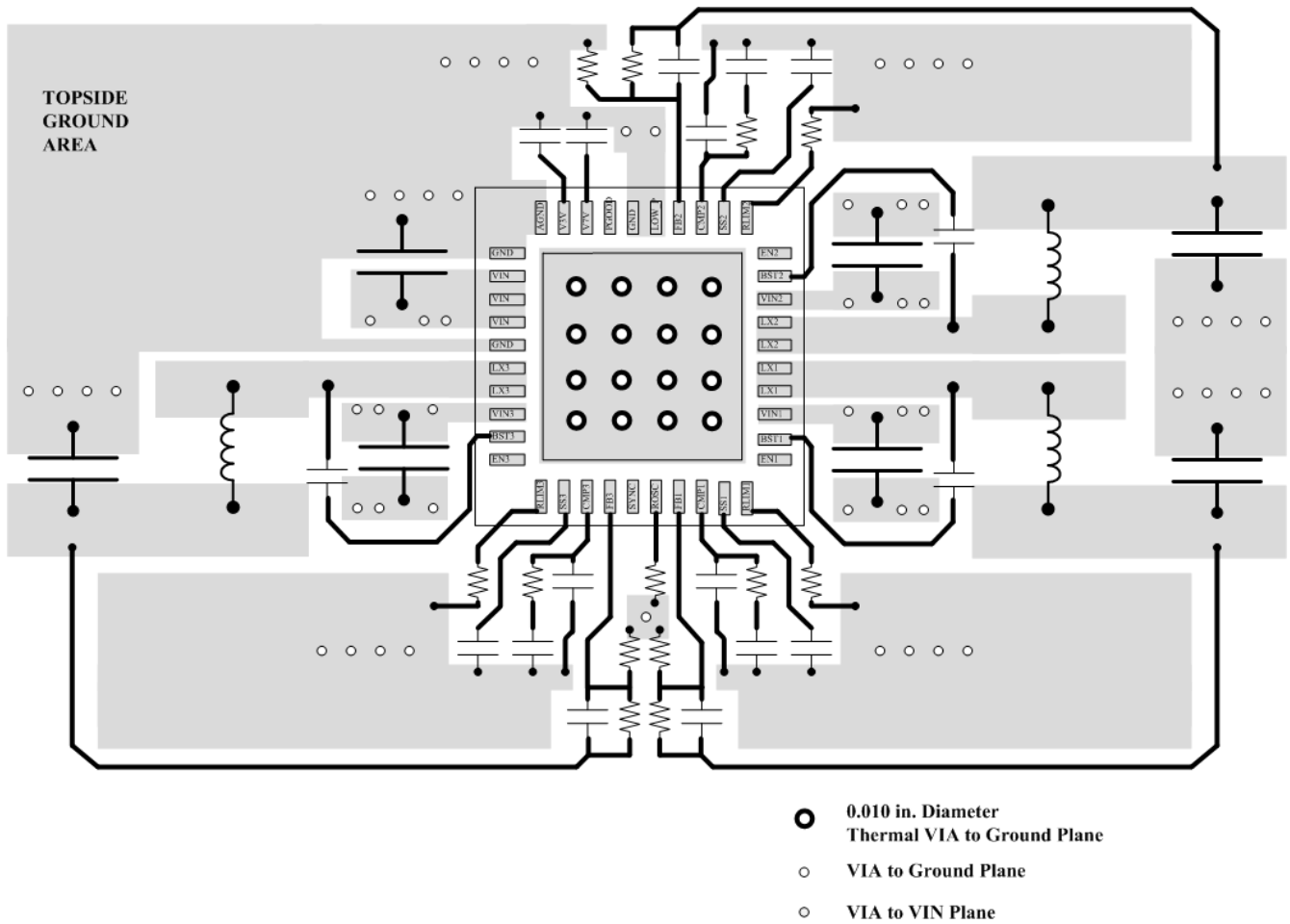
## 10 Layout

### 10.1 Layout Guidelines

Layout is a critical portion of PMIC designs.

- Place VOUT, and LX on the top layer and an inner power plane for VIN.
- Fit also on the top layer connections for the remaining pins of the PMIC and a large top side area filled with ground.
- The top layer ground area should be connected to the internal ground layer(s) using vias at the input bypass capacitor, the output filter capacitor and directly under the TPS65251-x device to provide a thermal path from the Powerpad land to ground.
- The AGND pin should be tied directly to the power pad under the IC and the power pad.
- For operation at full rated load, the top side ground area together with the internal ground plane, must provide adequate heat dissipating area.
- There are several signals paths that conduct fast changing currents or voltages that can interact with stray inductance or parasitic capacitance to generate noise or degrade the power supplies performance. To help eliminate these problems, the VIN pin should be bypassed to ground with a low ESR ceramic bypass capacitor with X5R or X7R dielectric. Care should be taken to minimize the loop area formed by the bypass capacitor connections, the VIN pins, and the ground connections. Since the LX connection is the switching node, the output inductor should be located close to the LX pins, and the area of the PCB conductor minimized to prevent excessive capacitive coupling.
- The output filter capacitor ground should use the same power ground trace as the VIN input bypass capacitor. Try to minimize this conductor length while maintaining adequate width.
- The compensation should be as close as possible to the COMP pins. The COMP and OSC pins are sensitive to noise so the components associated to these pins should be located as close as possible to the IC and routed with minimal lengths of trace.

## 10.2 Layout Example




**10-1. Layout Schematic**

## 11 Device and Documentation Support

### 11.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 11.2 サポート・リソース

[TI E2E™ サポート・フォーラム](#)は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の[使用条件](#)を参照してください。

### 11.3 Trademarks

Blu-ray™ is a trademark of Blu-ray Disc Association.

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

### 11.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 11.5 Glossary







[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2) | Lead finish/<br>Ball material<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples   |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|---|
| TPS65251-1RHAR   | ACTIVE        | VQFN         | RHA             | 40   | 2500        | RoHS & Green    | NIPDAU                               | Level-3-260C-168 HR  | -40 to 125   | TPS<br>65251-1          |  |
| TPS65251-1RHAT   | ACTIVE        | VQFN         | RHA             | 40   | 250         | RoHS & Green    | NIPDAU                               | Level-3-260C-168 HR  | -40 to 125   | TPS<br>65251-1          |  |
| TPS65251-2RHAR   | ACTIVE        | VQFN         | RHA             | 40   | 2500        | RoHS & Green    | NIPDAU                               | Level-3-260C-168 HR  | -40 to 125   | TPS<br>65251-2          |  |
| TPS65251-2RHAT   | ACTIVE        | VQFN         | RHA             | 40   | 250         | RoHS & Green    | NIPDAU                               | Level-3-260C-168 HR  | -40 to 125   | TPS<br>65251-2          |  |
| TPS65251-3RHAR   | ACTIVE        | VQFN         | RHA             | 40   | 2500        | RoHS & Green    | NIPDAU                               | Level-3-260C-168 HR  | -40 to 125   | TPS<br>65251-3          |  |
| TPS65251-3RHAT   | ACTIVE        | VQFN         | RHA             | 40   | 250         | RoHS & Green    | NIPDAU                               | Level-3-260C-168 HR  | -40 to 125   | TPS<br>65251-3          |  |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS65251-1RHAR | VQFN         | RHA             | 40   | 2500 | 330.0              | 16.4               | 6.3     | 6.3     | 1.1     | 12.0    | 16.0   | Q2            |
| TPS65251-1RHAT | VQFN         | RHA             | 40   | 250  | 180.0              | 16.4               | 6.3     | 6.3     | 1.1     | 12.0    | 16.0   | Q2            |
| TPS65251-2RHAR | VQFN         | RHA             | 40   | 2500 | 330.0              | 16.4               | 6.3     | 6.3     | 1.1     | 12.0    | 16.0   | Q2            |
| TPS65251-2RHAT | VQFN         | RHA             | 40   | 250  | 180.0              | 16.4               | 6.3     | 6.3     | 1.1     | 12.0    | 16.0   | Q2            |
| TPS65251-3RHAR | VQFN         | RHA             | 40   | 2500 | 330.0              | 16.4               | 6.3     | 6.3     | 1.1     | 12.0    | 16.0   | Q2            |
| TPS65251-3RHAT | VQFN         | RHA             | 40   | 250  | 180.0              | 16.4               | 6.3     | 6.3     | 1.1     | 12.0    | 16.0   | Q2            |

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS65251-1RHAR | VQFN         | RHA             | 40   | 2500 | 367.0       | 367.0      | 38.0        |
| TPS65251-1RHAT | VQFN         | RHA             | 40   | 250  | 210.0       | 185.0      | 35.0        |
| TPS65251-2RHAR | VQFN         | RHA             | 40   | 2500 | 367.0       | 367.0      | 38.0        |
| TPS65251-2RHAT | VQFN         | RHA             | 40   | 250  | 210.0       | 185.0      | 35.0        |
| TPS65251-3RHAR | VQFN         | RHA             | 40   | 2500 | 367.0       | 367.0      | 38.0        |
| TPS65251-3RHAT | VQFN         | RHA             | 40   | 250  | 210.0       | 185.0      | 35.0        |

## GENERIC PACKAGE VIEW

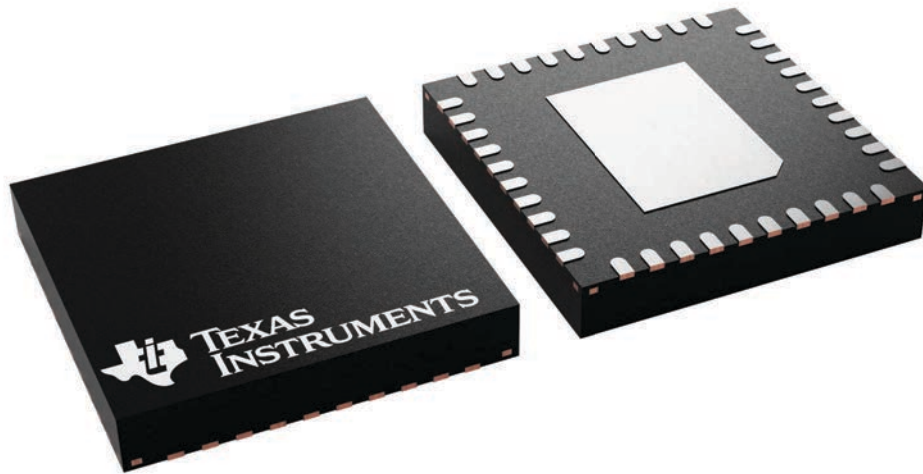
**RHA 40**

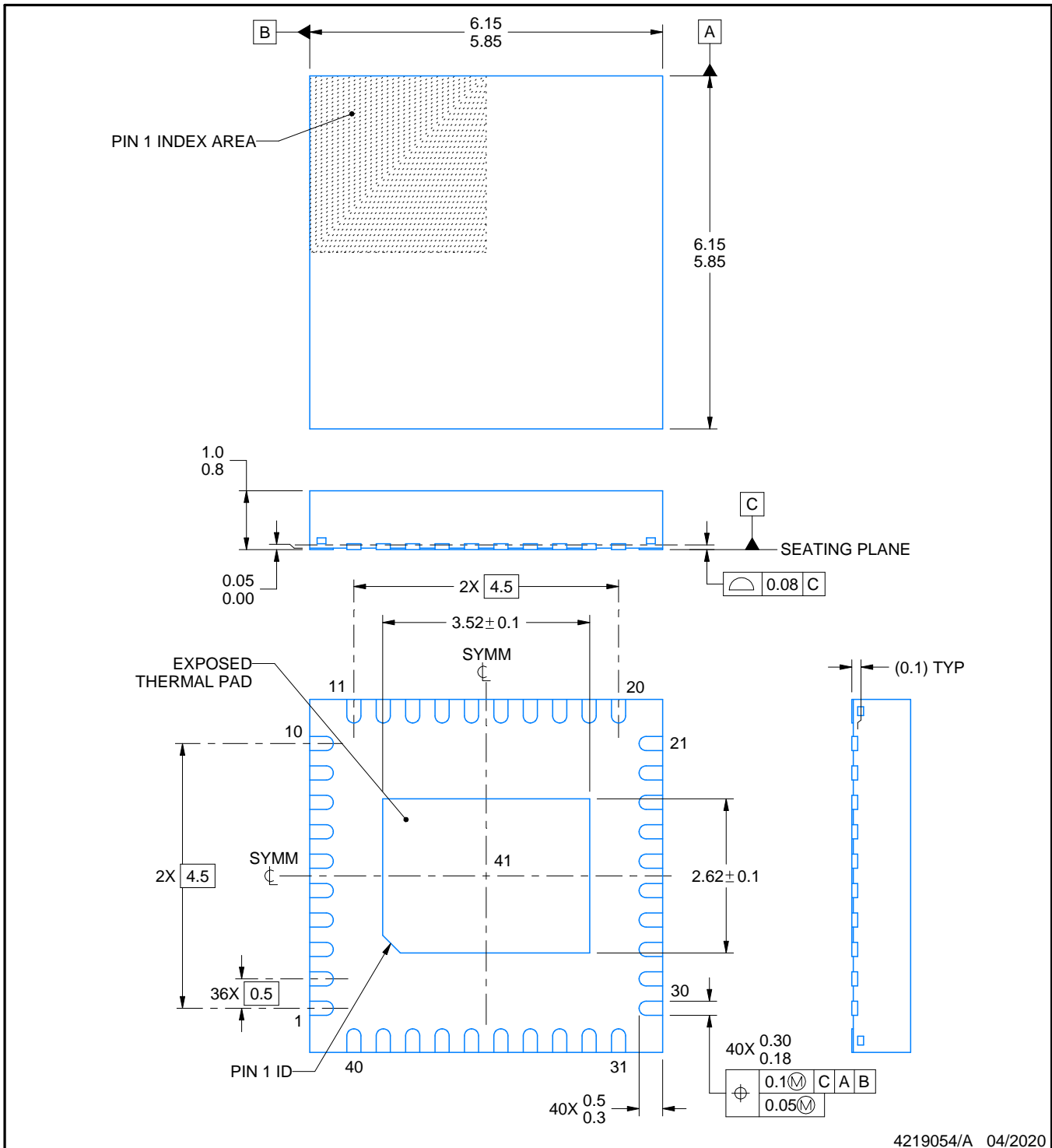
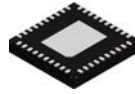
**VQFN - 1 mm max height**

6 x 6, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.





4219054/A 04/2020

NOTES:

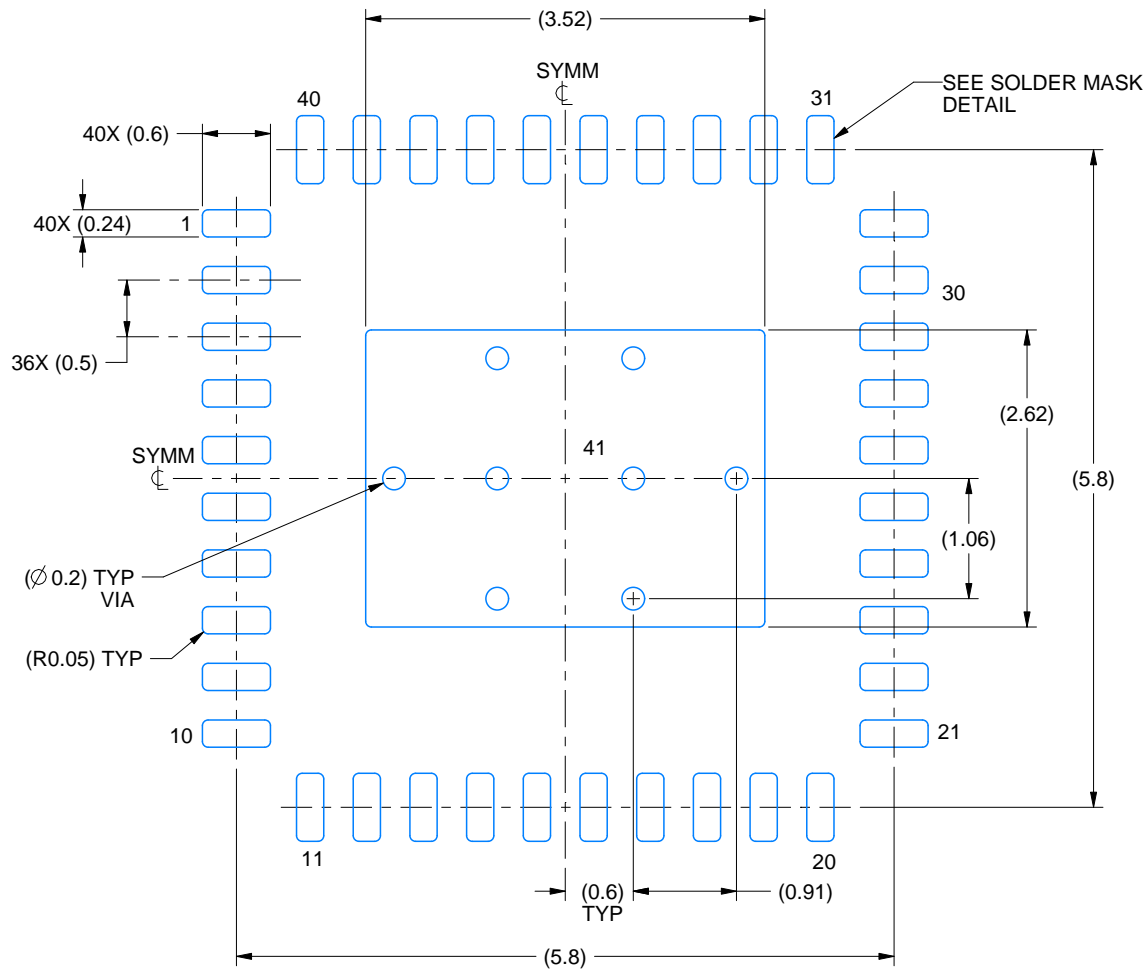
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

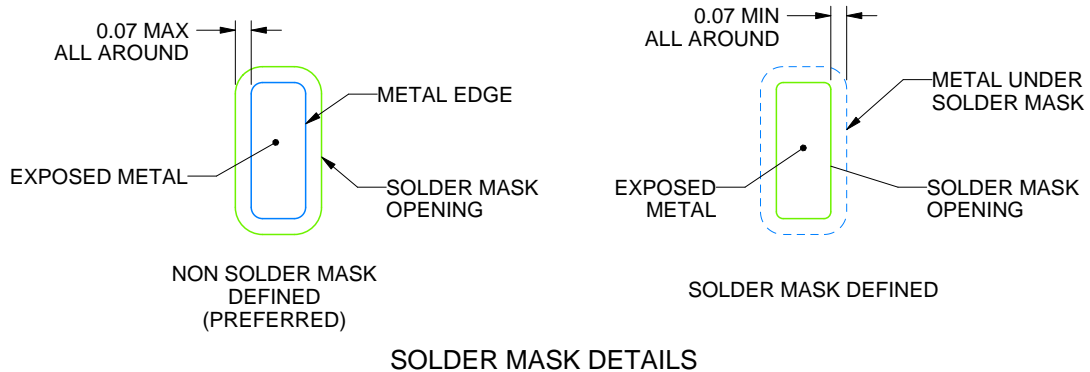
RHA0040E

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



4219054/A 04/2020

NOTES: (continued)

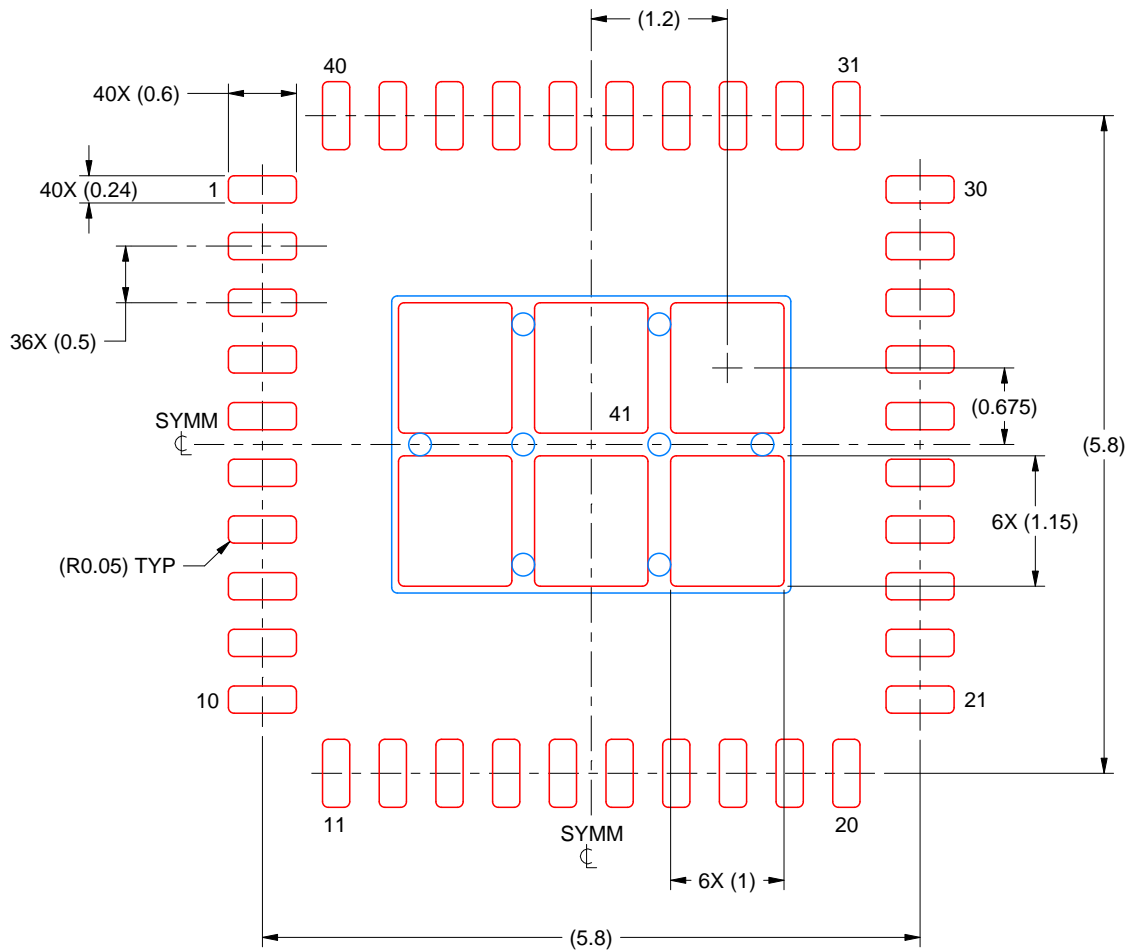
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RHA0040E

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 MM THICK STENCIL  
SCALE: 15X

EXPOSED PAD 41  
75% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4219054/A 04/2020

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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